DM3730/AM3703 Torpedo + Wireless SOM Hardware Specification

Hardware Documentation

Logic PD // Products
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Revision History

REV	EDITOR	REVISION DESCRIPTION	SCHEMATIC PN & REV	APPROVAL	DATE
1	NJK	Preliminary Release	1020029 Rev A	SO	09/07/11
2	NJK	-Table 2.4: Added information for antennas included in development kit; -Table 2.5: Added note 2; -Added Table 4.2: DSI Matched Pair Lengths; -Added Table 4.3: CSI2 Matched Pair Lengths; -Section 4.7.5.1: Updated reserved I2C3 addresses; -Section 7.2: Changed signal names for J2.79, J2.81, J2.82, J2.84, J2.94, and J2.96; -Table 7.1: Added additional resistors; -Table 7.2: Changed signal names for J2.79, J2.81, J2.82, J2.84, J2.94, and J2.96; -Appendix A: Updated mechanical drawings; -Appendix B: Added SOM retention methods drawings;	1020613 Rev A	NJK, RAH	11/10/11
3	SO, NJK	-Section 2.3.1and Section 2.3.2: Added information regarding TBD status of mechanical drawings; -Section 2.3.3: Added information regarding TBD status of example retention methods; -Section 2.4: Updated note 3; -Table 2.4: Updated antenna information; -Table 3.2: Added DC Main Battery idle and suspend power numbers for DM37x Linux BSP v2.0-5p1 and DM3730 Android Gingerbread 2.3.4 BSP v1.0; Added notes 6-8; -Added Section 4.3.3; -Appendix A: Replaced mechanical drawings with TBD notice; -Appendix B: Replaced retention methods drawings with TBD notice	1020613 Rev A	NJK	03/29/12
4	SO, NJK	-Section 1.4: Added reference to *DM3730 Torpedo + Wireless SOM Mechanical Hold-Down Scenarios WP* and *DM3730 Torpedo + Wireless SOM RF Grounding WP*; -Section 2.3.1and Section 2.3.2: Removed TBD status of mechanical drawings; -Section 2.3.3: Updated section to point to *DM3730 Torpedo + Wireless SOM Mechanical Hold-Down Scenarios WP* in place of Appendix B; -Section 4.3.3: Added important note regarding need for additional grounding; -Appendix A: Removed TBD status and added updated mechanical drawings; -Removed Appendix B	1021712 Rev A	NJK	04/25/12
5	SO	-Appendix A: Updated mechanical drawing	1021712 Rev A	SO	05/04/12

6	SO, NJK	-Throughout: Added language for AM3703 configuration of Torpedo + Wireless SOM; Updated baseboard references to Torpedo Launcher 3; -Section 1.2: Added PRCM; Removed PCMCIA; -Added Section 2.1.2; -Table 2.1: Updated weight and dimensions SOM to reflect addition of finger gaskets on bottom of SOM; -Section 2.3.1: Added note regarding height of mating plug/cable assembly; -Table 2.4: Updated cables and antennas included in development kit; -Table 3.2: Updated idle and suspend power numbers for DM37x Android Gingerbread 2.3.4 BSP v1.2 and DM37x Linux BSP v2.1-0; -Section 4.3: Added information regarding standard configuration DM3730/AM3703 Torpedo + Wireless SOMs in the Important Note; -Section 4.3.3: Changed acceptable cable length to 105mm instead of 50mm; -Section 7.2: Added note to description of J2.72, J2.74, J2.76 and J2.86 to leave unconnected if not in use; -Appendix A: Updated mechanical drawing	1021712 Rev A	NJK	07/03/12
A	SO, NJK	Official Release -Throughout: Added FCC/IC certification language; removed preliminary markings; -Figure 2.3: Removed I2C level shifter from block diagram; -Section 3: Added table note 9; -Table 3.2: Added information for GPS Active Antenna LDO Output Voltage; -Table 3.3: Updated RF performance numbers; -Section 4.3: Reorganized section to improve clarity and flow; -Section 4.3.3: Added note regarding *FCC/IC Certification Guidelines Application Note;* -Section 4.3.4: Added information about the ability of J8 to support an active antenna; added note that Logic PD has not tested GPS with a passive antenna; -Appendix A: Updated mechanical drawing	1021712 Rev A	NJK	09/11/12
B	SO, NJK	-Table 3.2: Updated idle and suspend power numbers for DM3730/AM3703 Android Gingerbread 2.3.4 BSP v1.4 and DM37x Linux BSP v2.3-2; -Table 3.3: Added note 1 to indicate data was achieved at nominal room temperature; -Section 4.8: Added note that proper USB adapter cable is necessary for USB 2.0 OTG to function as host; added link to Digi-Key adapter cable that supports host function; -Section 7: Added note regarding purpose of I/O column in pin description tables; -Section 7.1: Added processor pin for MCBSP3_DR (J1:77) to pinout table; -Section 7.2: Changed I/O column to input only for the non-default signals on J2:55, J2:57, J2:61, and J2:63; changed the I/O to output only for the non-default signals on J2:65, J2:67, J2:69, and J2:71; -Table 7.2: Changed I/O column to input only for the non-default signals on J2:55, J2:57, J2:61, and J2:63; changed the I/O to output only for the non-default signals on J2:65, J2:67, J2:69, and J2:71	1021712 Rev B	BSB, RAH	03/13/13
C	SO	-FCC Certification Statement: Added information regarding -IC Certification Statement: Added final paragraph regarding distance and co-location exposure requirements to statements in English and French; -Table 2.4: Added note 2 regarding appropriate routing of cables	1021712 Rev B	NJK	05/02/13

D	NJK	-Throughout: Updated for -31 version of DM3730/AM3703 Torpedo + Wireless SOM; -FCC Certification Statement: Added statement that use of the 5150-5250 MHz band is limited to indoor use only; -IC Certification Statement: Added approved radio transmitter for -31 version of SOM; added pulse electronics antenna to list of acceptable antennas for use; added statement that use of the 5150-5250 MHz band is limited to indoor use only; -Figure 2.1: Added additional 26 MHz oscillator to SOM block diagram; -Table 3.3: Updated to reflect typical numbers for -31 version of SOM; -Section 4.3.3: Added information regarding chip antenna for -31 version of SOM; -Table 4.3: Changed matched pair length for CS12_DXI/CS12_DY1 to 1282 -Table 7.1: Added note to description for pin J1.88 that it is used by software to control audio mute circuit on Torpedo Launcher 3 Baseboard; -Appendix A: Updated mechanical drawing	1023821 Rev B	KJH, RAH, SO	7/1/13

Please check the Logic PD website[1] for the latest revision of this specification and other documentation.

[1] www.logicpd.com

FCC Certification

This device complies with Part 15 of the FCC Rules. Operation is subject to the following two conditions:
1. This device may not cause harmful interference, and
2. This device must accept any interference received, including interference that may cause undesired operation.

Any changes or modifications not expressly approved by Logic PD could void the user's authority to use this device. See Logic PD's *AN 538 FCC/IC Certification Guidelines for End Products Using the DM3730/AM3703 Torpedo + Wireless SOM*[2] for additional information.

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to Part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one of the following measures:

—Reorient or relocate the receiving antenna.
—Increase the separation between the equipment and receiver.
—Connect the equipment to an outlet on a circuit different from that to which the receiver is connected.
—Consult the dealer or an experienced radio/television technician for help.

To comply with FCC/IC RF exposure requirements for mobile transmitting devices, this transmitter should only be used or installed at locations where there is at least 20 cm separation distance between the antenna and all persons.

To comply with FCC/IC RF exposure limits for general population / uncontrolled exposure, the antenna(s) used for this transmitter must be installed to provide a separation distance of at least 20 cm from all persons and must not be co-located or operating in conjunction with any other antenna or transmitter. Use of the 5150-5250 MHz band must also be limited to indoor use only.

IC Certification

Under Industry Canada regulations, this radio transmitter may only operate using an antenna of a type and maximum (or lesser) gain approved for the transmitter by Industry Canada. To reduce potential radio interference to other users, the antenna type and its gain should be so chosen that the equivalent isotropically radiated power (e.i.r.p.) is not more than that necessary for successful communication.

This radio transmitter (10029A-1021149 for -30 SOM model number, 10029A-1024119 for -31 SOM model number) has been approved by Industry Canada to operate with the antenna types listed below with the maximum permissible gain and required antenna impedance for each antenna type indicated. Antenna types not included in this list, having a gain greater than the maximum gain indicated for that type, are strictly prohibited for use with this device.

Antennas Acceptable for Use with Transmitter
— Ethertronics Prestta 1000418 and Sunridge Corporation U.FL-to-W.FL coaxial cable MCD-R1-60-105-MCBG; Max gain: 2.5 dBi at 2.4 GHz; 3.5 dBi at 5 GHz; Impedance: 50 ohms
— Pulse Electronics W3006 and Sunridge Corporation W.FL-to-W.FL coaxial cable MCD-DH-68-035A; Max gain: 3.2 dBi at 2.4 GHz; 4.2 dBi at 5 GHz; Impedance: 50 ohms

This device complies with Industry Canada License-exempt RSS standard(s). Operation is subject to the following two conditions:
1. This device may not cause interference, and
2. This device must accept any interference, including interference that may cause undesired operation of the device.

To satisfy IC RF exposure requirements for mobile and base station transmission devices, a separation distance of 20 cm or more should be maintained between the antenna of this device and persons during operation. To ensure compliance, operation at closer than this distance is not recommended. The antenna(s) used for this transmitter must

[2] http://support.logicpd.com/downloads/1547/

not be co-located or operating in conjunction with any other antenna or transmitter. Use of the 5150-5250 MHz band must also be limited to indoor use only.

Certification IC

Conformément à la réglementation d'Industrie Canada, le present émetteur radio peut fonctionner avec une antenne d'un type et d'un gain maximal (ou inférieur) approuvé pour l'émetteur par Industrie Canada. Dans le but de réduire les risques de brouillage radioélectrique à l'intention des autres utilisateurs, il faut choisir le type d'antenne et son gain de sorte que la puissance isotrope rayonnée équivalente (p.i.r.e.) ne dépasse pas l'intensité nécessaire à l'établissement d'une communication satisfaisante.

Le present émetteur radio (10029A-1021149 pour -30 numéro de modèle, 10029A-1024119 pour -31 numéro de modèle) a été approuvé par Industrie Canada pour fonctionner avec les types d'antenne énumérés ci-dessous et ayant un gain admissible maximal et l'impédance requise pour chaque type d'antenne. Les types d'antenne non inclus dans cette liste, ou dont le gain est supérieur au gain maximal indiqué, sont strictement interdits pour l'exploitation de l'émetteur.

Antennes Acceptable pour l'utilisation avec cet émetteur radio

— Ethertronics Prestta 1000418 et Sunridge Corporation U.FL à W.FL câble coaxial MCD-R1-60-105-MCBG. Gain superieur: 2.5 dBi à 2.4 GHz; 3.5 dBi à 5 GHz; L'impédance: 50 ohms

— Pulse Electronics W3006 et Sunridge Corporation W.FL à W.FL câble coaxial MCD-DH-68-035A. Gain superieur: 3.2 dBi à 2.4 GHz; 4.2 dBi à 5 GHz; L'impédance: 50 ohms

Le present appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'utilisation est autorisée aux deux conditions suivantes :

1. L'appareil ne doit pas produire de brouillage, et
2. L'appareil doit accepter tout brouillage radioélectrique subi, meme si le brouillage peut compromettre le fonctionnement.

Pour répondre à la IC d'exposition pour les besoins de base et mobiles dispositifs de transmission de la station, sur une distance de séparation de 20 cm ou plus doit être maintenue entre l'antenne de cet appareil et les personnes en cours de fonctionnement. Pour assurer le respect, l'exploitation de plus près à cette distance n'est pas recommandée. L'antenne (s) utilisé pour cet émetteur ne doit pas être co-localisés ou fonctionner conjointement avec une autre antenne ou transmetteur. L'utilisation de la bande de 5150-5250 MHz doit également être limitée à l'utilisation d'intérieur seulement.

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1 Introduction

1.1 Product Overview

The DM3730/AM3703 Torpedo + Wireless System on Module (SOM) is an ultra-compact form factor built around Texas Instruments' (TI) DaVinci™ DM3730 processor and WiLink™ 7.0 wireless solution. Confining these two systems to a single board isolates the complex design, manufacturing, and wireless certifications from the rest of your product.

The DM3730/AM3703 Torpedo + Wireless SOM occupies less than one square inch, but boasts PC-like speeds up to 1 GHz with long battery life. Partnered with such high performance is a startlingly low power consumption in suspend state. This balance of speed and power is accomplished through Logic PD's vast system design experience; understanding the most detailed workings of each component and their interaction with one another creates a product that operates at optimal efficiency.

The WL1283 wireless chipset provides access to all the wireless protocols required in today's connected world. 802.11a/b/g/n, Bluetooth, and GPS signals are natively integrated with the DM3730/AM3703 Torpedo + Wireless SOM and Logic PD Board Support Packages (BSPs).

By using the same connectors as Logic PD's existing OMAP35x and DM3730/AM3703 Torpedo SOMs, the DM3730/AM3703 Torpedo + Wireless SOM extends the roadmaps of existing products and provides an upgrade path from today's products to future technologies.

The ultra-compact DM3730/AM3703 Torpedo + Wireless SOM is an ideal off-the-shelf solution for applications in markets where network connectivity is required and space is a premium. From point-of-care medical products to handheld communication devices, the DM3730/AM3703 Torpedo + Wireless SOM allows for the powerful versatility and compact designs needed in today's market-changing products.

1.2 Abbreviations, Acronyms, & Definitions

ADC	Analog to Digital Converter
BSP	Board Support Package
BTB	Board-to-Board
DDR	Double Data Rate (RAM)
DMA	Direct Memory Access
ESD	Electrostatic Discharge
FIFO	First In First Out
GPI	General Purpose Input
GPIO	General Purpose Input Output
GPMC	General Purpose Memory Controller
GPO	General Purpose Output
I2C	Inter-Integrated Circuit
I2S	Inter-Integrated Circuit Sound
IC	Integrated Circuit
I/O	Input/Output
IRQ	Interrupt Request
LCD	Liquid Crystal Display
LDO	Low Dropout (Regulator)

McBSP	Multi-channel Buffered Serial Port
OTG	On-the-Go (USB)
PCB	Printed Circuit Board
PHY	Physical Layer
PLL	Phase Lock Loop
PoP	Package on Package
PRCM	Power Reset Clock Manager
PWM	Pulse Width Modulation
RTC	Real Time Clock
SDIO	Secure Digital Input Output
SDRAM	Synchronous Dynamic Random Access Memory
SOM	System on Module
SSP	Synchronous Serial Port
SPI	Standard Programming Interface
STN	Super-Twisted Nematic (LCD)
TFT	Thin Film Transistor (LCD)
TI	Texas Instruments
TSC	Touch Screen Controller
TTL	Transistor-Transistor Logic
UART	Universal Asynchronous Receive Transmit

1.3 Scope of Document

This hardware specification is unique to the design and use of the DM3730/AM3703 Torpedo + Wireless SOM as designed by Logic PD and does not intend to include information outside of that scope. Detailed information about the TI DM3730/AM3703 processors or any other device component on the SOM can be found in their respective manuals and specification documents. Please see Section 1.4 for additional resources.

1.4 Additional Documentation Resources

The following documents or documentation resources are referenced within this hardware specification:

- TI's *DM3730, DM3725 Digital Media Processors Datasheet*[3]
- TI's *AM3715, AM3703 Sitara ARM Microprocessors Datasheet*[4]
- TI's *AM/DM37x Multimedia Device Technical Reference Manual (TRM)*[3]
- TI's *TPS65950 Data Manual*[5]
- TI's *TPS65950 OMAP Power Management and System Companion Device TRM*[5]
- USB 2.0 Specification,[6] available from USB.org
- Logic PD's Hardware Design Files (BOM, Schematic, and Layout) for all boards included in the development kit (baseboard, SOM, LCD), as well as all standard configuration SOMs. Sign into your account[7] on Logic PD's website to access these files.

[3] http://www.ti.com/product/dm3730#technicaldocuments
[4] http://focus.ti.com/docs/prod/folders/print/am3703.html#technicaldocuments
[5] http://www.ti.com/product/tps65950#technicaldocuments
[6] http://www.usb.org/developers/docs/

- Logic PD's *LogicLoader v2.5 User Guide*[8]
- Logic PD's *WP 505 DM3730/AM3703 Torpedo + Wireless SOM Mechanical Hold-Down Scenarios*[9]
- Logic PD's *WP 537 DM3730/AM3703 Torpedo + Wireless SOM RF Grounding*[10]
- Logic PD's *AN 538 FCC/IC Certification Guidelines for End Products Using the DM3730/AM3703 Torpedo + Wireless SOM*[11]

[7] http://support.logicpd.com/auth/
[8] http://support.logicpd.com/downloads/1428/
[9] http://support.logicpd.com/downloads/1481/
[10] http://support.logicpd.com/downloads/1545/
[11] http://support.logicpd.com/downloads/1547/

2 Functional Specification

2.1 Processor

The Torpedo + Wireless SOM uses TI's DaVinci™ DM3730 and Sitara™ AM3703 processors. The DM3730 is viewed as the superset configuration; the AM3703 does not include a DSP core or graphics accelerator.

2.1.1 DM3730 Processor Highlights

This list comes from TI's DM3730 Digital Media Processor product page.[12] See TI documentation for more details.

- Compatible with OMAP™ 3 Architecture
- ARM® microprocessor (MPU) Subsystem
  - Up to 1 GHz ARM® Cortex™-A8 Core; Also supports 300, 600, and 800 MHz
  - NEON SIMD Coprocessor
- High-Performance Image, Video, Audio (IVA2.2™) Accelerator Subsystem
  - Up to 800 MHz TMS320C64x+™ DSP Core
  - Enhanced Direct Memory Access (EDMA) Controller (128 Independent Channels)
  - Video Hardware Accelerators
- POWER SGX™ Graphics Accelerator (DM3730 only)
  - Tile Based Architecture Delivering up to 20 MPoly/sec
  - Universal Scalable Shader Engine: Multi-threaded Engine Incorporating Pixel and Vertex Shader Functionality
  - Industry Standard API Support: OpenGLES 1.1 and 2.0, OpenVG1.0
  - Fine-Grained Task Switching, Load Balancing, and Power Management
  - Programmable High-Quality Image Anti-Aliasing
- Advanced Very-Long-Instruction-Word (VLIW) TMS320C64x+™ DSP Core
  - Eight Highly-Independent Functional Units
  - Six ALUs (32-/40-bit); Each Supports Single 32-bit, Dual 16-bit, or Quad 8-bit, Arithmetic per Clock Cycle
  - Two Multipliers Support Four 16 × 16-bit Multiplies (32-Bit Results) per Clock Cycle or Eight 8 × 8-bit Multiplies (16-bit Results) per Clock Cycle
  - Load-Store Architecture With Non-Aligned Support

[12] http://focus.ti.com/docs/prod/folders/print/dm3730.html

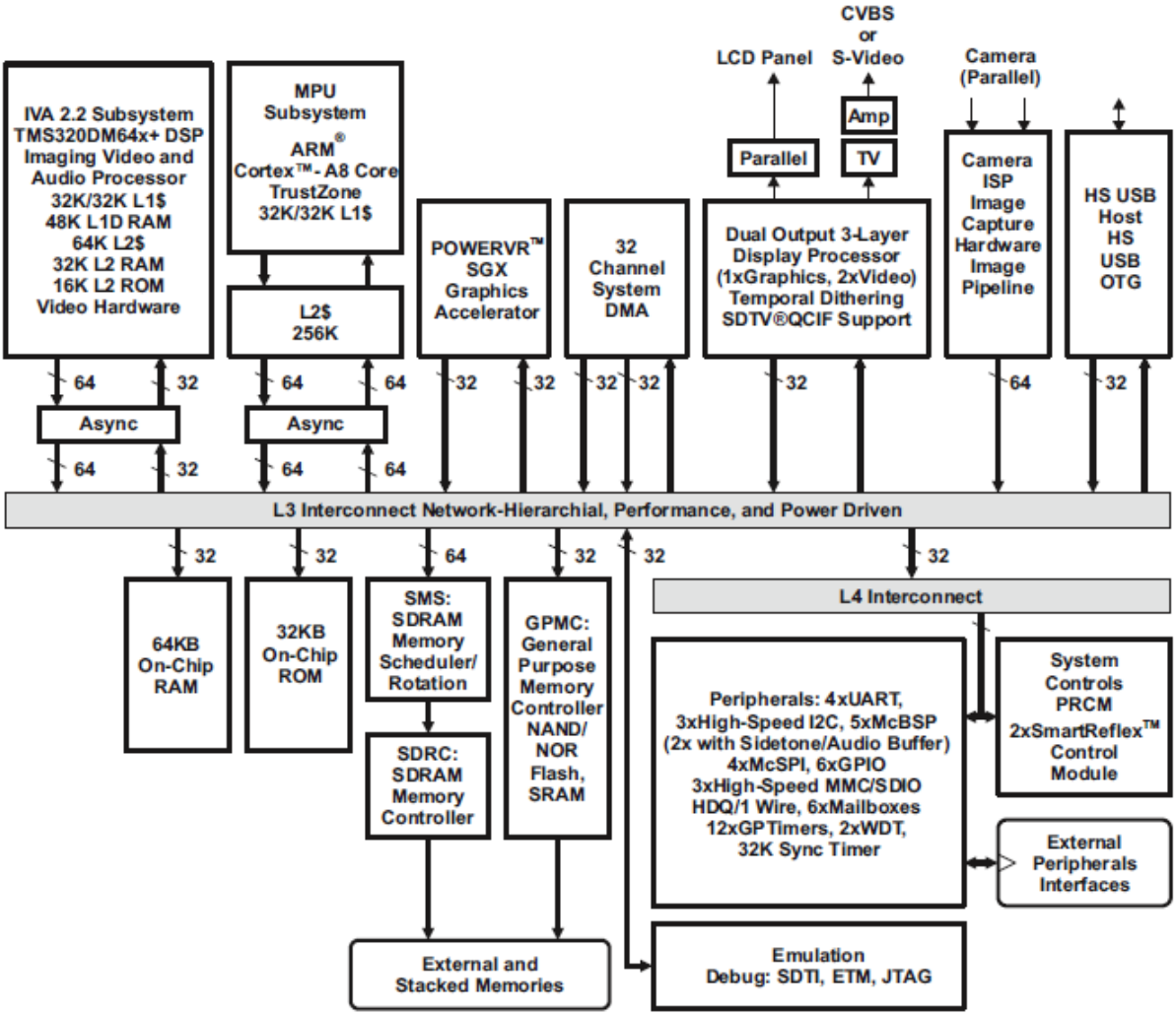


Figure 2.1: DM3730 Processor Block Diagram

NOTE: The block diagram pictured above comes from TI's *DM3730, DM3725 Digital Media Processors Datasheet* (Literature Number: SPRS685D).

2.1.2 AM3703 Processor Highlights

This list comes from TI's AM3703 Digital Media Processor product page.[13] See TI documentation for more details.

- Compatible to OMAP™ 3 Architecture
- MPU Subsystem
  - Up to 1-GHz Sitara™ ARM® Cortex™-A8 Core Also supports 300, 600, and 800-MHz operation
  - NEON SIMD Coprocessor

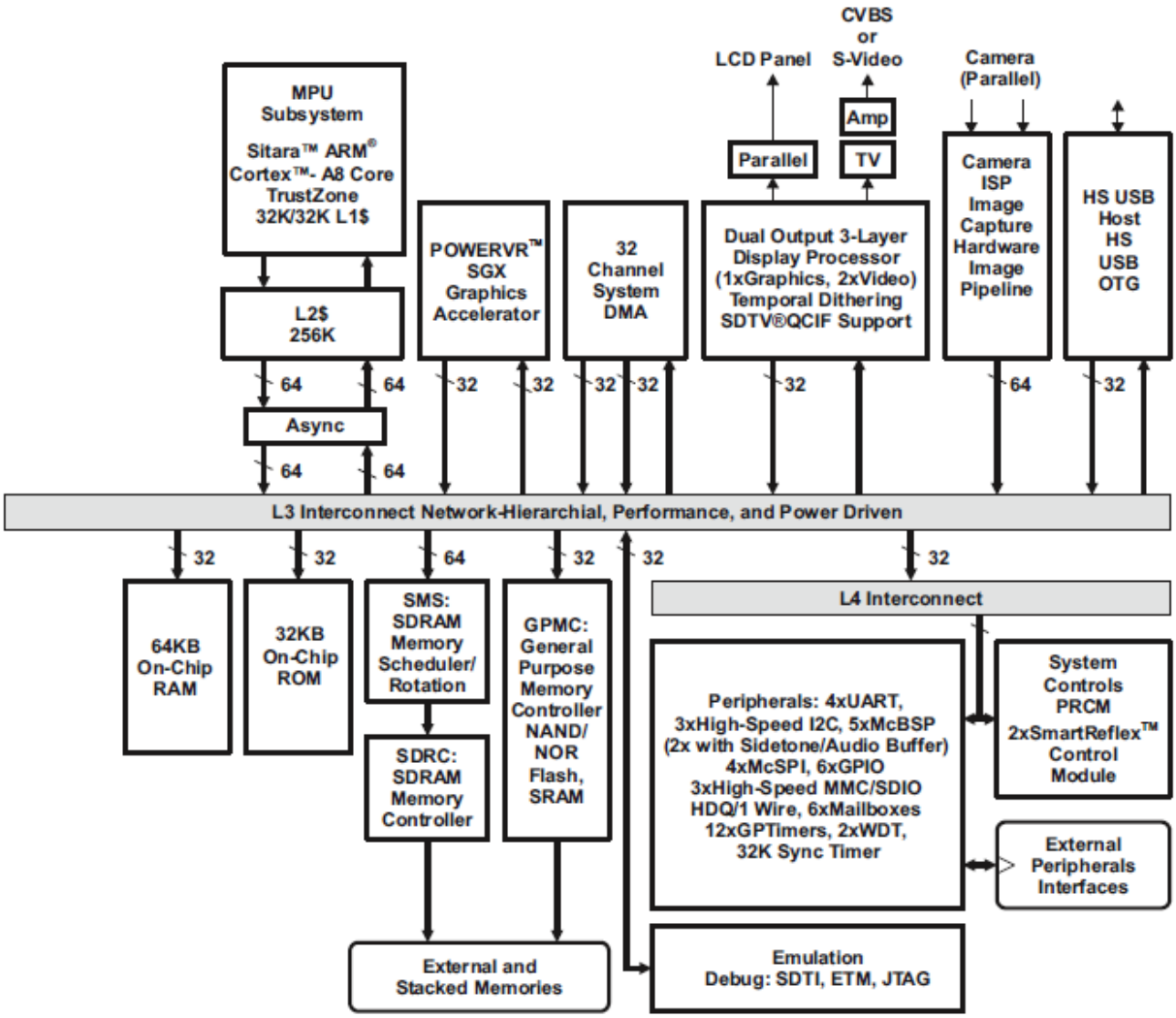


Figure 2.2: AM3703 Processor Block Diagram

[13] http://focus.ti.com/docs/prod/folders/print/am3703.html

NOTE: The block diagram pictured above comes from TI's *AM3715, AM3703 Sitara ARM Microprocessors Datasheet* (Literature Number: SPRS616F).

2.2 Torpedo + Wireless SOM Interface

Logic PD's common Torpedo + Wireless SOM interface allows for easy migration to new processors and technology. Logic PD is constantly researching and developing new technologies to improve performance, lower cost, and increase feature capabilities. By using the common Torpedo + Wireless SOM footprint, it may be possible to take advantage of Logic PD's work without having to re-spin the old design.

In fact, encapsulating a significant amount of your design onto the Torpedo + Wireless SOM reduces any long-term risk of obsolescence. If a component on the Torpedo + Wireless SOM design becomes obsolete, Logic PD will design for an alternative part that is as transparent as possible to your product. Furthermore, Logic PD tests all SOMs prior to delivery, decreasing time-to-market and ensuring a simpler and less costly manufacturing process. Contact Logic PD[14] for more information.

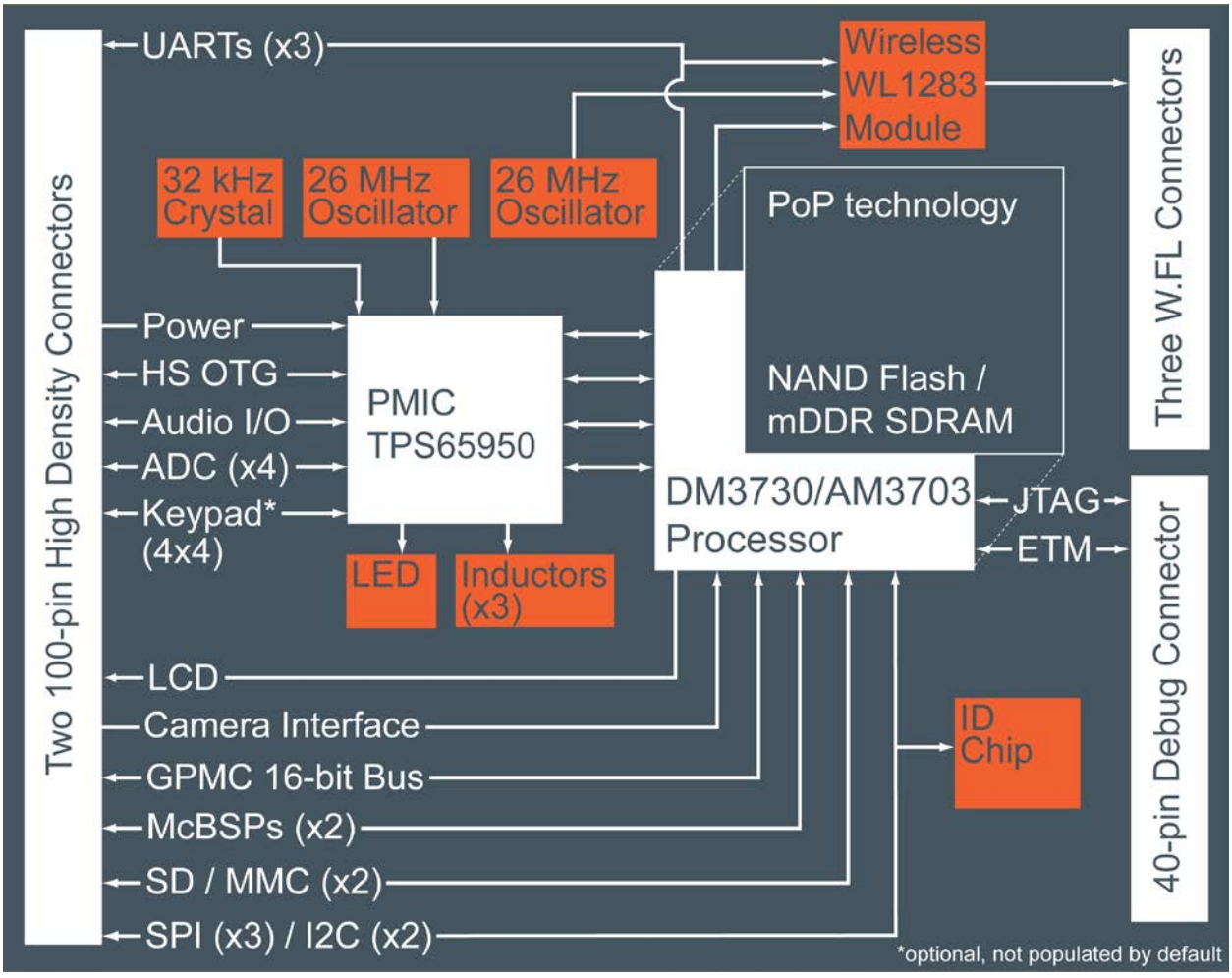


Figure 2.3: DM3730/AM3703 Torpedo + Wireless SOM Block Diagram

[14] http://support.logicpd.com/support/askaquestion.php

2.3 Mechanical Specifications

Table 2.1: Mechanical Characteristics of SOM

Parameter	Min	Typical	Max	Unit	Notes
Dimensions	—	15.0 x 33.0 x 3.8	—	mm	1
Weight	—	2.6	—	Grams	2
Connector Insertion/Removal	—	30	—	Cycles	—

TABLE NOTES:

1. This height of 3.8 mm reflects the mated height of the SOM when connected to the baseboard. When the SOM is not connected to the baseboard, the uncompressed finger gaskets increase the height to 4.7 mm.

2. May vary depending on SOM configuration.

The DM3730/AM3703 Torpedo + Wireless SOM connects to a PCB baseboard through two 100-pin board-to-board (BTB) socket connectors.

Table 2.2: Baseboard Mating Connectors

Ref Designator	Manufacturer	Torpedo + Wireless Connector P/N	Mating Connector P/N
J1, J2	Hirose	DF40C-100DP-0.4V(51)	DF40C-100DS-0.4V(51)

2.3.1 Wireless Mechanical Specification

The DM3730/AM3703 Torpedo + Wireless SOM mechanical drawings included in Appendix A show the locations of the 2.4 GHz (J7), 5 GHz (J6), and GPS (J8) signal antenna connectors on the bottom side of the PCB. Table 2.3 below contains the manufacturer information for the PCB connectors on the DM3730/AM3703 Torpedo + Wireless SOM.

Table 2.3: Antenna PCB Connectors

Ref Designator	Manufacturer	P/N
J6, J7, J8	Hirose	W.FL-R-SMT-1

Table 2.4 below contains the manufacturer information for the cables and antennas that Logic PD provides in the Zoom DM3730 Torpedo Development Kit.

NOTE: To comply with the United States of America Federal Communications Commission (FCC) and Industry Canada (IC) certifications already obtained by Logic PD on the DM3730/AM3703 Torpedo + Wireless SOM, the Wi-Fi and Bluetooth cables and antennas selected for an end product must meet FCC/IC guidelines as described in Section 4.3.3.

Table 2.4: Cables and Antennas Included in Development Kit

Ref Designator	Manufacturer	P/N	Notes
Dual-Band Antenna	Ethertronics, Inc.	1000418	—
W.FL-to-U.FL Cable	Sunridge Corporation	MCD-R1-60-105-MCBG	—
W.FL-to-RP-SMA Cable	Sunridge Corporation	MCD-RH-60-100-SMAJB181	—
GPS Antenna	Taoglas	AA.105.301111	—
GPS W.FL-to-SMA Cable	Sunridge Corporation	MCD-RH-60-120-SMAJX105-R1	3

TABLE NOTES:

1. General note: The mating plug/cable assembly must meet the SOM stack height of 1.5 mm.

2. General note: When connected, cables must be routed so as not to make contact with components on the SOM to prevent accidental shorting; contact with the SOM finger gaskets is acceptable.

3. This cable is soldered to the baseboard.

2.3.2 DM3730/AM3703 Torpedo + Wireless SOM Mechanical Drawings

Please see Appendix A for mechanical drawings of the DM3730/AM3703 Torpedo + Wireless SOM and recommended baseboard footprint layout.

2.3.3 Example DM3730/AM3703 Torpedo + Wireless SOM Retention Methods

Logic PD has developed several methods to secure the DM3730/AM3703 Torpedo + Wireless SOM in an end product. For mechanical drawings of these example retention methods, please see *WP 505 DM3730/AM3703 Torpedo + Wireless SOM Mechanical Hold-Down Scenarios.*

2.4 Temperature Specifications

Table 2.5: Temperature Characteristics of SOM

Parameter	Min	Typical	Max	Unit	Notes
Commercial Operating Junction Temperature	0	—	90	°C	1
Industrial Operating Junction Temperature	-40	—	105	°C	1, 2
Wireless Operating Temperature	-40		85	°C	3, 4, 5
Storage Temperature	-40	25	85	°C	—

TABLE NOTES:

1. Junction temperature of the DM3730/AM3703.

2. Junction temperature of the DM3730/AM3703 processor must stay below 90°C in OPP130 or OPP1G.

3. Full WLAN performance is available at Tambient -30°C to 60°C; outside of this temperature range, WLAN performance is reduced.

4. The D7002 device can be operated for seven years at Tambient of 85°C, assuming 25% active mode and 75% sleep mode (15,400 cumulative active power-on hours).

5. The D7002 device can be operated for 5,000 cumulative active WLAN hours at Tambient of 85°C.

3 Electrical Specification

Table 3.1: Absolute Maximum Ratings

Parameter	Symbol	Rating	Unit
DC Main Battery Input Voltage	MAIN_BATTERY	0.0 to 4.5	V
DC USB1_VBUS Input Voltage	USB1_VBUS	0.0 to 7.0	V
RTC Backup Battery Voltage	BACKUP_BATT	0.0 to 3.3	V

NOTE: These stress ratings are only for transient conditions. Operation at or beyond absolute maximum rating conditions may affect reliability and cause permanent damage to the DM3730/AM3703 Torpedo + Wireless SOM and its components.

Table 3.2: Recommended Operating Conditions

Parameter	Min	Typical	Max	Unit	Notes
DC Main Battery Input Voltage	**2.7*** (see note 3)	3.3	4.5	V	3, 5
DC Main Battery Idle Power, Linux	—	276.5	—	mW	6
DC Main Battery Idle Power, Android	—	295.1	—	mW	7
DC Main Battery Suspend Power, Linux	—	—	12.4	mW	6,8
DC Main Battery Suspend Power, Android	—	—	9.9	mW	7,8
DC USB1_VBUS Input Voltage	4.4	5.0	7.0	V	—
DC RTC Backup Battery Voltage	1.8	3.2	3.3	V	—
Input Signal High Voltage	0.65 x VREF	—	VREF	V	2, 4
Input Signal Low Voltage	-0.3	—	0.35 x VREF	V	2, 4
Output Signal High Voltage	VREF - 0.2	—	VREF	V	2, 4
Output Signal Low Voltage	GND	—	0.2	V	4
GPS Active Antenna LDO Output Voltage	1.0	—	3.15	V	9

TABLE NOTES:

1. General note: CPU power rails are sequenced on the SOM.
2. VREF represents the peripheral I/O supply reference for the specific CPU voltage rail.
3. 2.7V is the minimum threshold for the battery at which the device will power OFF. However, the minimum voltage at which the device will power ON (if PWRON does not have a switch and is connected to MAIN_BATTERY) is 3.2V ±100 mV, assuming battery plug-in at the same time as the device switch-on event. If PWRON has a switch, then 3.2V is the minimum for the device to turn ON.

4. The exact minimum and maximum values depend on the specific pin being referenced. Please refer to TI's *DM3730, DM3725 Digital Media Processors Datasheet* and *TPS65950 Data Manual* for exact values.

5. Full WLAN performance is specified over DC Main Battery Input Voltage range from 3.0V to 4.5V.

6. Running the DM37x Linux BSP v2.3-2 on the standard DM3730 Torpedo + Wireless SOM configuration included in the Zoom DM3730 Torpedo Development Kit. Idle power was measured at the command prompt after a fresh boot. Suspend power was measured after pressing the S2 button to enter suspend. Wattson™, Logic PD's power measurement and performance monitoring application, was used to record all numbers.

7. Running the DM3730/AM3703 Android Gingerbread 2.3.4 BSP v1.4 on the standard DM3730 Torpedo + Wireless SOM configuration included in the Zoom DM3730 Torpedo Development Kit. Idle power was measured at the home screen after a fresh boot. Suspend power was measured after pressing the S2 button to enter suspend. Wattson™, Logic PD's power measurement and performance monitoring application, was used to record all numbers.

8. Suspend power numbers were taken with the versions of Logic PD's BSPs noted above in notes 6 and 7. Logic PD is continually improving the suspend power consumption through software updates. Logic PD's BSPs are also written for general use cases; the BSP may be further customized to offer lower suspend power numbers. Please contact Logic PD for more information on low-power software offerings.

9. Supplied by the TPS65950 LDO VMMC2. Please see TI's *TPS65950 OMAP Power Management and System Companion Device TRM* for more information about controlling this LDO.

Table 3.3: RF Performance

Parameter	Typical	Unit	Notes
802.11b/g/n Transmit Power	+17.6 +12.9 +12.0	dBm	1, 2, 5.5, & 11 Mbps 48 Mbps & 54 Mbps MCS7
802.11b/g/n Receive Sensitivity	-94.7 -72.9 -69.63	dBm	1 Mbps DSS 54 Mbps OFDM MCS7
802.11a/n Transmit Power	+17.2 +13.6 +12.7	dBm	6 Mbps, 9 Mbps 48 Mbps, 54 Mbps MCS7
802.11a/n Receive Sensitivity	-72.1 -68.7	dBm	54 Mbps OFDM MCS7
BT Transmit Power	+3.1 +0.5 +0.8	dBm	GFSK EDR, Pi/4-DQPSK EDR, 8DPSK
BT Receive Sensitivity	-89.6 -89.9 -83.4	dBm	GFSK, BER=0.1% Pi/4-DQPSK, BER = 0.01% 8DPSK, BER = 0.01%
BLE Transmit Power	+2.8	dBm	
BLE Receive Sensitivity	-93.1	dBm	PER = 30.8%
GPS Total Channel Gain (voltage gain)[2]	+72	dB	Measured at VGA output, with VGA gain at 20 dB
GPS Input Return Loss[2]	-12	dB	Single-ended with external matching network to 50 ohms

TABLE NOTES:

1. General note: Data in the *Typical* column was achieved at nominal room temperature (23°C).

2. GPS performance numbers were taken from the *Epcos D7002 Module Datasheet* (Rev 1.0).

4 Peripheral Specification

4.1 Clocks

The DM3730/AM3703 processor requires an oscillator and crystal to enable proper internal timing. A 26.000 MHz oscillator is used to generate many of the processor's internal clocks via a series of Phase Lock Loops (PLLs) and signal dividers. To generate the core CPU clock, the 26.000 MHz signal is run through a Digital PLL controlled by the PRCM registers. Divisors are used to divide down the internal bus frequency to set the LCD, memory controller, camera interface, etc.

IMPORTANT NOTE: Please see TI's *AM/DM37x Multimedia Device TRM* for additional information about processor clocking.

The second required crystal runs at 32.768 kHz and is connected directly to the TPS65950 PMIC. The 32.768 kHz clock is used for PMIC and CPU start-up and as a reference clock for the Real Time Clock (RTC) Module.

The CPU's microcontroller core clock speed is initialized by software on the DM3730/AM3703 Torpedo + Wireless SOM. The SDRAM bus speed is set at 200 MHz in LogicLoader. Other clock speeds, such as core speed and specific serial baud rates, can be supported and modified in the software for specific user applications.

The DM3730/AM3703 Torpedo + Wireless SOM provides an external bus clock, uP_BUS_CLK. This clock is driven by the GPMC_CLK pin.

Table 4.1: Processor Clock Specifications

DM3730/AM3703 Processor Signal Name	DM3730/AM3703 Torpedo + Wireless SOM Net Name	Default Software Value in LogicLoader
CORE	N/A	Up to 1 GHz
SDRC_CLK	N/A	200 MHz
GPMC_CLK	uP_BUS_CLK	Not configured

4.2 Memory

4.2.1 Package on Package Memory (Mobile DDR and NAND)

The DM3730/AM3703 processor uses Package on Package (PoP) technology to stack BGA memory devices on top of the CPU BGA. The processor uses a 32-bit memory bus to interface to mobile DDR (mDDR) SDRAM and a 16-bit memory bus to interface to NAND.

Logic PD's default memory configuration on the DM3730/AM3703 Torpedo + Wireless SOM is 256 MB mDDR and 512 MB NAND.

4.2.2 External Memory

It is possible to expand the system's non-volatile storage capability by adding external flash ICs, SD memory, CompactFlash, or NAND flash. Please contact Logic PD for other possible peripheral designs.

4.3 Wireless

The DM3730/AM3703 Torpedo + Wireless SOM uses an Epcos D7002 WLAN/GPS/BT wireless module to provide an easy-to-use wireless networking interface. The D7002 supports IEEE802.11a/b/g, IEEE802.11n, Bluetooth, and GPS interfaces.

IMPORTANT NOTE: When using the wireless module, an additional grounding path is needed from the DM3730/AM3703 Torpedo + Wireless SOM to the baseboard to ensure consistent operation. Standard configurations of the DM3730/AM3703 Torpedo + Wireless SOM include two finger gaskets on the bottom of the SOM to serve this purpose. Please see Logic PD's *WP 537 DM3730/AM3703 Torpedo + Wireless SOM RF Grounding* for additional information on the finger gaskets and other available grounding options.

4.3.1 802.11 Wireless Ethernet

The D7002 is connected to the DM3730/AM3703 processor through SDIO3 for 802.11 communication. The antenna connectors are located on the PCB at reference designator J6 for 5 GHz and J7 for 2.4 GHz; **NOTE:** J7 is shared with Bluetooth.

4.3.2 Bluetooth

The D7002 is connected to the DM3730/AM3703 processor through UARTC (processor UART2) and to the PCM interface of the TPS65950 for Bluetooth support. The antenna connector is located on the PCB at reference designator J7, shared with 2.4 GHz 802.11.

4.3.3 2.4 GHz and 5 GHz Antenna Information

The DM3730/AM3703 Torpedo + Wireless SOM has been qualified to use the Ethertronics 1000418 dual-band antenna with 2.5 dBi peak gain at 2.4 GHz and 3.5 dBi peak gain at 5 GHz. Use of these antennas with a W.FL-to-U.FL cable length of 105 mm or longer will satisfy FCC/IC regulations. If an antenna with a higher gain, of a different type, or with a shorter W.FL-to-U.FL cable is to be used, the end product may be subject to intentional radiation testing at a qualified test lab. Logic PD suggests consulting with a qualified test lab before making any changes to the antenna system.

Logic PD highly recommends the use of the antenna specified above for most applications. However, for space constrained applications, Logic PD has also qualified a specific chip antenna for use with the -31 version of the DM3730/AM3703 Torpedo + Wireless SOM. In these applications, the chip antenna is located on the host board and very specific guidelines for the feed trace to the antenna must be followed. For this reason, all host board designs must be approved and signed off by Logic PD prior to production. This design approval will require a Logic PD support contract.

Please refer to Logic PD's *AN 538 FCC/IC Certification Guidelines for End Products Using the DM3730/AM3703 Torpedo + Wireless SOM* for more information about the antennas approved for use.

4.3.4 GPS

The GPS component of the D7002 uses the same UARTC interface as Bluetooth for communication to the DM3730/AM3703 processor. The antenna connector is located on the PCB at reference designator J8. J8 supports an active antenna through the use of LDO VMMC2 from the TPS65950. **NOTE:** Logic PD has not tested GPS with a passive antenna.

Access to the GPS enable signal (BT_EN) and UARTC is provided on SOM connector J1 to allow access to the GPS interface when the DM3730/AM3703 processor is in a low-power mode. If the processor pins are left as tri-state before going to a low-power mode and the main clock is left on, an external master may control the GPS interface.

4.4 Audio Codec

The DM3730/AM3703 processor has multiple Multi-channel Buffered Serial Port (McBSP) interfaces that support PCM and I2S formats. Both PCM and I2S serial paths drive the built-in TPS65950 audio codec. From the TPS65950 PMIC, the outputs are CODEC_OUTL and CODEC_OUTR; these signals are available from the expansion connectors.

The codec in the TPS65950 PMIC performs up to full-duplex codec functions and supports variable sample rates from 8–96k samples per second. See the “Audio” chapter in TI’s *TPS65950 OMAP Power Management and System Companion Device TRM* for more information.

NOTE: The DM3730/AM3703 Torpedo + Wireless SOM also offers alternate serial interfaces for other codec devices. If you are looking for a different codec option, Logic PD has previously interfaced different high-performance audio codecs into other SOMs. Contact Logic PD for assistance in selecting an appropriate audio codec for your application.

4.5 Display Interface

The DM3730/AM3703 processor has a built-in LCD controller supporting STN, color STN, and TFT panels at a resolution of up to HD 720p, 1280 x 720 x 24-bit color. The LCD signals are available in up to 24 bits of parallel data or up to two data-configurable lanes (plus clock signaling) of MIPI DSI serial data. The signals from the DM3730/AM3703 LCD controller are organized by bit and color and can be interfaced through the J1 and J2 connectors on the SOM (see Section 7). See TI’s *AM/DM37x Multimedia Device TRM* for additional information on the integrated LCD controller.

Logic PD has written drivers for panels of different types and sizes. Please contact Logic PD before selecting a panel for your application.

IMPORTANT NOTE: Using the internal graphics controller will affect processor performance. Selecting display resolutions and color bits per pixel will vary processor busload.

IMPORTANT NOTE: The MIPI DSI pairs must be routed as 100 ohm differential pairs on the baseboard PCB. The length difference between the individual DSI pairs must be matched on the baseboard; this match must take into account the length differences on the SOM. Length matching numbers for the DM3730/AM3703 Torpedo + Wireless SOM can be found in Table 4.2 below.

Table 4.2: DSI Matched Pair Lengths

DM3730/AM3703 Torpedo + Wireless SOM DSI Pair Names	Matched Pair Length (Mils)
DSI_DX0/DSI_DY0	532
DSI_DX1/DSI_DY1	266
DSI_DX2/DSI_DY2	338

4.6 Camera Interface

The DM3730/AM3703 processors have a camera image signal processor (ISP2P) that is used for image capture. The ISP2P supports a parallel interface (up to 12-bits) as well as a MIPI CSI2 serial interface (up to two data-configurable links plus clock signaling). Both interfaces are available through the J1 and J2 connectors on the SOM (see Section 7). See TI's *AM/DM37x Multimedia Device TRM* for additional information on the ISP2P.

IMPORTANT NOTE: The MIPI CSI2 pairs must be routed as 100 ohm differential pairs on the baseboard PCB. The length difference between the individual CSI2 pairs must be matched on the baseboard; this match must take into account the length differences on the SOM. Length matching numbers for the DM3730/AM3703 Torpedo + Wireless SOM can be found in Table 4.3 below.

Table 4.3: CSI2 Matched Pair Lengths

DM3730/AM3703 Torpedo + Wireless SOM CSI2 Pair Names	Matched Pair Length (Mils)
CSI2_DX0/CSI2_DY0	1185
CSI2_DX1/CSI2_DY1	1282
CSI_D0/CSI_D1 (CSI2_DX2/CSI2_DY2)	260

4.7 Serial Interfaces

The DM3730/AM3703 Torpedo + Wireless SOM comes with the following serial channels: UARTA, UARTB, UARTC, three SPI ports, two McBSP, and two I2C ports. If additional serial channels are required, please contact Logic PD for reference designs. Please see TI's *AM/DM37x Multimedia Device TRM* for additional information regarding serial communications.

4.7.1 UARTA

UARTA has been configured as the main DM3730/AM3703 Torpedo + Wireless SOM serial port based on the processor UART1. It is an asynchronous 16C750-compatible UART. This UART provides a high-speed serial interface that uses 64 byte First In / First Out (FIFO) and is capable of sending and receiving serial data simultaneously. The signals from the DM3730/AM3703

Torpedo + Wireless SOM are 1.8V Transistor-Transistor Logic (TTL) level signals, not RS232 level signals. The end-product design must provide an external RS232 transceiver for RS232 applications. Logic PD has provided an example reference design in the *Torpedo Launcher 3 Baseboard Schematic*, available in the DM3730 Torpedo Development Kit Hardware Design Files. When choosing an RS232 transceiver, the designer should keep cost, availability, ESD protection, and data rates in mind.

The UARTA baud rate is set to a default of 115.2 Kbit/sec, though it supports most common serial baud rates.

4.7.2 UARTB

Serial port UARTB (processor UART3) is an asynchronous 16C750-compatible UART. This UART is a high-speed serial interface that uses FIFO and is capable of sending and receiving serial data simultaneously. The signals from the DM3730/AM3703 Torpedo + Wireless SOM are 1.8V TTL level signals, not RS232 level signals. The UARTB baud rate can also be set to most common serial baud rates.

4.7.3 UARTC

IMPORTANT NOTE: UARTC is connected to the wireless module D7002. It should not be used for anything other than communication to the wireless module. When the processor is in a low-power mode, the UARTC signals may be tristated on the processor such that an external master could communicate with the D7002 wireless module.

Serial port UARTC (processor UART2) is an asynchronous 16C750-compatible UART. This UART is a high-speed serial interface that uses FIFO and is capable of sending and receiving serial data simultaneously. The signals from the DM3730/AM3703 Torpedo + Wireless SOM are 1.8V TTL level signals, not RS232 level signals. The UARTC baud rate can also be set to most common serial baud rates.

4.7.4 McSPI

The DM3730/AM3703 Torpedo + Wireless SOM provides three external SPI ports with multiple chip selects. Additional SPI ports are available through different resistor populations. Please see Table 7.1 for more information.

4.7.5 I2C

The DM3730/AM3703 Torpedo + Wireless SOM supports two dedicated external I2C ports. The clock and data signals for the I2C2 and I2C3 ports have 4.7K ohm pull-up resistors. Please see TI's *AM/DM37x Multimedia Device TRM* for additional information.

4.7.5.1 Reserved I2C Addresses

The DM3730/AM3703 Torpedo + Wireless SOM contains a product ID chip that connects to the I2C3 bus. Logic PD software uses this product ID chip to determine hardware version information. As a result, the 7-bit I2C3 address listed below is used by the product ID chip and must be avoided in custom designs:

101 0000

4.8 USB Interface

The DM3730/AM3703 Torpedo + Wireless SOM supports one USB 2.0 OTG port, which can function as a host or device/client. In order for the port to operate as a host, a proper adapter cable must be used; Logic PD recommends one similar to the USB adapter cable by Digi-Key[15] (part number 10-00003-ND).

The port can operate at up to 480 Mbit/sec. The USB controller for the OTG port is internal to the processor; an external PHY built into the TPS65950 PMIC supports the OTG port. For more information on using the OTG interfaces, please see TI's *AM/DM37x Multimedia Device TRM*.

IMPORTANT NOTE: In order to correctly implement USB on the DM3730/AM3703 Torpedo + Wireless SOM, additional impedance matching circuitry may be required on the USB1_D+ and USB1_D- signals before they can be used. USB 2.0 requirements specify the signals must be routed as differential pairs with 90 ohm differential impedance. Refer to the *USB 2.0 Specification* document for detailed information.

4.9 General Purpose I/O

Logic PD designed the DM3730/AM3703 Torpedo + Wireless SOM to be flexible and provide multiple options for analog and digital GPIO. There are numerous digital GPIO pins on the DM3730/AM3703 Torpedo + Wireless SOM that interface to the DM3730/AM3703 processor and TPS65950 PMIC; please see Section 7 for more information. If certain peripherals are not desired, such as the LCD controller, chip selects, IRQs, or UARTs, more GPIO pins become available.

DESIGN NOTE: Due to buffer strength, an external serial resistor must be connected to the BGA balls where GPIO_120 through GPIO_127 and GPIO_129 are muxed with MMC/SIM signals. See Section 25.2 in TI's *DM3730, DM3725 Digital Media Processors Datasheet* (Literature Number: SPRUGN4K) for additional information.

4.10 Expansion/Feature Options

The DM3730/AM3703 Torpedo + Wireless SOM was designed for expansion and a variable feature set, providing all the necessary control signals and bus signals to expand the user's design. It is possible for a user to expand the DM3730/AM3703 Torpedo + Wireless SOM's functionality even further by adding host bus devices. Some features that are implemented on the DM3730/AM3703 processors but are not discussed herein include: RTC, pulse width modulation

[15] http://www.digikey.com/scripts/DkSearch/dksus.dll?WT.z_header=search_go&lang=en&keywords=10-00003-ND&x=0&y=0&cur=USD

(PWM), Secure Digital, MMC cards, SDIO cards, graphics accelerator, DSP codecs, Image Processing Unit, 1wire interface, and the debug module. For more details, see TI's *AM/DM37x Multimedia Device TRM* and Logic PD's *DM3730/AM3703 Torpedo + Wireless SOM Schematic*, available in the DM3730 Torpedo Development Kit Hardware Design Files download. Logic PD has experience implementing additional options, including other audio codecs, Ethernet ICs, co-processors, and components on SOMs. Please contact Logic PD for potential reference designs before selecting your peripherals.

5 System Integration

5.1 Configuration

The DM3730/AM3703 Torpedo + Wireless SOM was designed to meet multiple applications for users with specific design and budget requirements. As a result, this DM3730/AM3703 Torpedo + Wireless SOM supports a variety of embedded operating systems and hardware configurations. Please contact Logic PD if you have additional hardware configurations that are needed to meet your specific application needs.

5.2 Resets

The DM3730/AM3703 Torpedo + Wireless SOM has a reset input (MSTR_nRST) and a reset output (SYS_nRESWARM). External devices can drive MSTR_nRST low to assert reset to the product. The DM3730/AM3703 Torpedo + Wireless SOM uses SYS_nRESWARM to indicate to other devices that the DM3730/AM3703 Torpedo + Wireless SOM is in reset.

5.2.1 Master Reset (MSTR_nRST)—Reset Input

Logic PD suggests that custom designs implementing the DM3730/AM3703 Torpedo + Wireless SOM use the MSTR_nRST signal as the “pin-hole” reset used in commercial embedded systems. The MSTR_nRST triggers a power-on reset event in the processor and resets the entire CPU.

A low pulse on the MSTR_nRST signal, asserted by an external source (for example, the reset button on the custom design application), will bring MSTR_nRST low until the assertion source is de-asserted. There is no delay beyond the de-assertion of the external MSTR_nRST signal source, so the custom design must ensure that the assertion time is sufficient for all related peripherals.

Logic PD suggests that for any external assertion source that triggers the MSTR_nRST signal, analog or digital, de-bouncing should be used to generate a clean, one-shot reset signal.

IMPORTANT NOTE: MSTR_nRST does not reset the TPS65950 PMIC; the TPS65950 is only reset by removing power from the SOM. Any custom reset circuit design should guard against the assertion of the reset lines during a low-power state. This is because some of the critical system power rails may have been turned off in the TPS65950 when entering the low-power state; toggling the MSTR_nRST line will reset the processor, but not the TPS65950, leaving some of the critical system power rails off.

5.2.2 DM3730/AM3703 Torpedo + Wireless SOM Reset (SYS_nRESWARM)—Reset output

All hardware peripherals should connect their hardware-reset pin to the SYS_nRESWARM signal on the SOM’s J2 connector. Internally, all DM3730/AM3703 Torpedo + Wireless SOM peripheral hardware reset pins are connected to the SYS_nRESWARM net.

5.3 Interrupts

The DM3730/AM3703 processor incorporates the ARM Cortex-A8 interrupt controller which provides many inter-system interrupt sources and destinations. Most external GPIO signals can also be configured as interrupt inputs by configuring their pin control registers. Logic PD BSPs set up and process all onboard system and external DM3730/AM3703 Torpedo + Wireless SOM interrupt sources. See TI's *AM/DM37x Multimedia Device TRM* for additional information on using interrupts.

5.4 JTAG Debugger Interface

The JTAG connection to the DM3730/AM3703 Torpedo + Wireless SOM allows recovery of corrupted flash memory, real-time application debug, and DSP development (on the DM3730/AM3703 processor). There are several third-party JTAG debuggers available for TI microcontrollers. The following signals make up the JTAG interface to the DM3730/AM3703 processor: TDI, TMS, TCK, TDO, nTRST, RTCK, EMU0, and EMU1. These signals are routed to reference designator J5 on the SOM.

IMPORTANT NOTE: When laying out the 20-pin connector, realize that it may not be numbered as a standard 20-pin 0.1" insulation displacement connector (IDC) through-hole connector. See the *ETM Adapter Board Schematic*, available in the DM3730 Torpedo Development Kit Hardware Design Files download, for further details. Each JTAG tool vendor may define the 20-pin IDC connector pin-out differently.

5.5 ETM Adapter Interface

The Embedded Trace Macrocell (ETM) interface signals are available through connector J5 on the DM3730/AM3703 Torpedo + Wireless SOM. Logic PD developed an adapter board, included with the Zoom DM3730 Torpedo Development Kit, that converts the available signals on J5 to the standard Mictor connector interface used by most common third-party ETM tool providers. The connector supports ETM_D[15:0], ETM_CLK, ETM_CTL, and the JTAG signals listed in Section 5.4.

5.6 Power Supplies

In order to ensure a flexible design, the DM3730/AM3703 Torpedo + Wireless SOM has the following power areas: MAIN_BATTERY and BACKUP_BATT. All power areas are inputs to the DM3730/AM3703 Torpedo + Wireless SOM. The module also provides VIO_1V8 as a reference voltage. It may be used to supply up to 200 mA of power, although using an external supply is recommended.

5.6.1 MAIN_BATTERY

The MAIN_BATTERY input is the main source of power for the DM3730/AM3703 Torpedo + Wireless SOM. This input expects a voltage within typical single lithium-ion battery limits which generally operate from 2.7V to 4.2V. The TPS65950 power management controller takes the MAIN_BATTERY rail input and creates all onboard voltages. If MAIN_BATTERY is taken away, the processor cannot be woken up and has to go through a power-on reset sequence once MAIN_BATTERY returns.

5.6.2 BACKUP_BATT

The BACKUP_BATT power rail is used to power the onboard TPS65950 PMIC, power management state machine, and RTC circuit when MAIN_BATTERY is not present. Always power this rail to maintain the clock and power state of the product. A lithium-ion coin cell typically supplies power to this rail. The TPS65950 PMIC overrides this input when MAIN_BATTERY is applied.

5.7 System Power Management

Good power management design is important in any system development and embedded system design is no exception. In embedded system design, power management is typically one of the most complicated areas due to the dramatic effect it has on product cost, performance, usability, and overall customer satisfaction. Many factors affect a power-efficient hardware design: power supply selection (efficiency), clocking design, IC and component selection, etc. The DM3730/AM3703 Torpedo + Wireless SOM was designed with these aspects in mind, while also providing maximum flexibility in software and system integration.

On the DM3730/AM3703 Torpedo + Wireless SOM, there are many different software configurations that drastically affect power consumption: microcontroller core clock frequency; bus clock frequency; peripheral clocks; bus modes; power-management states; peripheral power states and modes; product user scenarios; interrupt handling; and display settings (resolution, backlight, refresh, bits per pixel, etc). These settings are typically initialized in the startup software routines and may be modified later in the operating system and application software. Information for these items can be found in the appropriate documents such as the *LogicLoader v2.5 User Guide* or the specific BSP manual.

5.7.1 T2_REGEN

T2_REGEN is an open-drain output from the TPS65950 PMIC. It can be used to control power for external power ICs or LDOs during both startup sequencing and low-power modes where external supplies may be turned off for additional power savings. Please see the *TPS65950 OMAP Power Management and System Companion Device TRM* for more information.

5.7.2 PWRON

The PWRON signal may be used to power on/off the SOM only after MAIN_BATTERY has been supplied to the SOM. Software must also set up the signal before it becomes a valid power switch. MAIN_BATTERY must be supplied to the SOM at all times when using the PWRON signal to power on/off the SOM. Please see the *TPS65950 OMAP Power Management and System Companion Device TRM* for more information.

5.8 Processor Power Management

The DM3730/AM3703 processor’s power management scheme was designed for the cellular handset market. This means the static and dynamic power consumption has very flexible controls, allowing designers to tweak the processor to minimize end-product power consumption. Logic PD software BSPs take advantage of Dynamic Voltage and Frequency Scaling (DVFS), Adaptive Voltage Scaling (AVS), and Dynamic Power Switching (DPS) to maximize power savings.

IMPORTANT NOTE: Sections 5.8.1 through 5.8.4 provide an overview of the features of the DM3730/AM3703 processor. Please refer to the specific BSP manual for more information on how each BSP supports these features and to TI's *AM/DM37x Multimedia Device TRM* for more information on each feature.

5.8.1 Dynamic Voltage and Frequency Scaling

DVFS is a method of changing the operating performance point (OPP) depending upon the task that is being performed. The lowest OPP is chosen such that a task will be completed in a given amount of time. By choosing the lowest OPP necessary to complete a task, a large amount of power is saved.

5.8.2 Adaptive Voltage Scaling

AVS is implemented on the DM3730/AM3703 processor through SmartReflex. AVS fine tunes the core voltages (VDD1_CORE and VDD2_CORE) to match the current operating frequency. AVS accounts for silicon differences between processors and allows the core voltages to run at the minimum voltage level on a per-silicon basis.

5.8.3 Dynamic Power Switching

DPS can be used to put sections of the DM3730/AM3703 processor into low-power states while it is waiting for a new task—for example, waiting for a timer or peripheral interrupt. DPS is different from DVFS and AVS because the power savings are realized while the DM3730/AM3703 processor is idle rather than actively completing a task.

5.8.4 Static Power Consumption Management

Static power consumption is managed by putting the DM3730/AM3703 processor into standby, suspend, or deep sleep modes. This helps reduce static power loss due to leakage in the processor and reduce overall power by turning off sections of the processor (the wakeup domain is kept powered). Using standby and suspend provides a quicker wakeup response than does completely cutting power to the SOM.

5.9 Boot Modes

The DM3730/AM3703 processor provides the option of booting from multiple sources. The boot mode is controlled by the SYS_BOOT pins of the processor. SYS_BOOT0, SYS_BOOT1 and SYS_BOOT3 through SYS_BOOT5 are available off-board through the J1 and J2 connectors on the SOM. Please see TI's *AM/DM37x Multimedia Device TRM* for further information. Common boot options are shown in Table 5.1 below.

NOTE: The SYS_BOOT pins of the processor are shared with the parallel display interface. Take care to ensure the boot strapping does not interfere with the display operation. The display must also not interfere with the SYS_BOOT pins during reset.

Table 5.1: Signals for Multiple Boot Sources

	DM3730/AM3703 Processor Pins	Boot Method
Default	SYS_BOOT[6:0] =1101111	USB, UART3, MMC1, NAND
Alternate	SYS_BOOT[6:0] =1001111	NAND, USB, UART3, MMC1
Alternate	SYS_BOOT[6:0] =1001110	XIPwait, DOC, USB, UART3, MMC1
Alternate	SYS_BOOT[6:0] =1000110	MMC1, USB

5.10 ESD Considerations

The DM3730/AM3703 Torpedo + Wireless SOM was designed to interface to a customer's baseboard, while remaining low in cost and adaptable to many different applications. The DM3730/AM3703 Torpedo + Wireless SOM does not provide any onboard ESD protection circuitry; this must be provided by the product it is used in. Logic PD has extensive experience in designing products with ESD requirements. Please contact Logic PD if you need any assistance in ESD design considerations.

6 Memory & I/O Mapping

On the DM3730/AM3703 processor, all address mapping for the GPMC chip select signals is listed below. Mapped chip select signals for the processor are available as outputs and are assigned as described in Table 6.1.

Table 6.1: Chip Select Signals

Chip Select	Device/Feature	Notes
nCS0	POP NAND	Boot chip select for PoP NAND device
nCS1	uP_nCS1	Available for use by an off-board external device
nCS2	uP_nCS2	Available for use by an off-board external device
nCS3	uP_nCS3	Available for use by an off-board external device
nCS4	uP_nCS4	Available for use by an off-board external device
nCS5	uP_nCS5	Available for use by an off-board external device
nCS6	uP_nCS6	Available for use by an off-board external device

NOTE: Memory addresses for chip selects on the DM3730/AM3703 Torpedo + Wireless SOM are configurable by software; therefore, precise address locations cannot be provided.

7 Pin Descriptions & Functions

IMPORTANT NOTE: The following pin descriptions and states are provided for the default pin usage for the Torpedo + Wireless form factor. Many of the signals defined in the connector tables can be configured as input or outputs—most GPIOs on the DM3730/AM3703 processor can be configured as either inputs or outputs—and have different functions. The *I/O* column in the pin description tables below refers to the default signal usage; processor I/O capability may be different. It is critical to review all signals in the final design (both electrical and software) to verify the necessary configuration (external pull-ups/pull-downs).

IMPORTANT NOTE: Please pay special attention to the reference voltage used to power each signal in the table below, especially when used as a GPIO. Not all power rails coming out of the TPS65950 PMIC are on by default and may need to be enabled through software. Reference voltages for DM3730/AM3703 processor signals can be found in Table 2-1 of TI's *DM3730, DM3725 Digital Media Processors Datasheet* or *AM3715, AM3703 Sitara ARM Microprocessor Datasheet*.

7.1 J1 Connector 100-Pin Descriptions

J1 Pin#	Signal Name	BGA Ball#	Processor Signal	I/O	Voltage	Description
1	uP_nWE	F4	GPMC_nWE	O	1.8V	Low indicates processor is writing. High indicates processor is reading. (See notes 1 & 2)
2	CODEC_OUTL	B4 (PMIC)	HSOL (PMIC)	O	max 2.7V	Left channel headset out.
3	VMMC1	K25 C2 (PMIC)	VDDS_MMC1 VMMC1.OUT (PMIC)	O	3.0V (configurable)	MMC/SD1 interface voltage reference output.
4	CODEC_INR	G1 (PMIC)	AUXR (PMIC)	I	max 2.7V	Auxiliary right channel line-in.
5	PWRON	A11 (PMIC)	PWRON (PMIC)	I	Max 4.5V (MAIN_BATTERY)	Active low. Software can use this signal as an interrupt to transition to RUN state from lower power states. Software is required for proper operation. This signal has a 4.7K pull up.
6	CODEC_INL	F1 (PMIC)	AUXL (PMIC)	I	max 2.7V	Auxiliary left channel line-in.
7	uP_A9	L3	GPMC_A9/ SYS_nDMAREQ2/ GPIO_42	O	1.8V	Processor GPMC bus address bit 9.
8	MIC_IN	E3 (PMIC)	HSMIC.P (PMIC)	I	max 2.7V	Microphone input.
9	uP_nCS0	G4	GPMC_nCS0	O	1.8V	uP_nCS0 is used by the PoP NAND flash device. This signal MUST be left unconnected, unless the PoP chip does not contain NAND. (See note 1)
10	CODEC_OUTR	B5 (PMIC)	HSOR (PMIC)	O	max 2.7V	Right channel headset out.
11	uP_nCS1	H3	GPMC_nCS1/GPIO_52	O	1.8V	External chip select available for customer use.
12	DGND	(See Schematic)	(See Schematic)	I	GND	Ground. Connect to digital ground.
13	uP_A8	M3	GPMC_A8/GPIO_41	O	1.8V	Processor GPMC bus address bit 8.

J1 Pin#	Signal Name	BGA Ball#	Processor Signal	I/O	Voltage	Description
14	MAIN_BATTERY	(See Schematic)	(See Schematic)	I	max 4.5V	External power source input. This signal should be driven directly by a single cell lithium-ion battery or a fixed regulated power source.
15	uP_nOE	G2	GPMC_nOE	O	1.8V	Active low. Used to indicate processor is reading from external devices. (See notes 1 & 2)
16	MAIN_BATTERY	(See Schematic)	(See Schematic)	I	max 4.5V	External power source input. This signal should be driven directly by a single cell lithium-ion battery or a fixed regulated power source.
17	DGND	(See Schematic)	(See Schematic)	I	GND	Ground. Connect to digital ground.
18	MAIN_BATTERY	(See Schematic)	(See Schematic)	I	max 4.5V	External power source input. This signal should be driven directly by a single cell lithium-ion battery or a fixed regulated power source.
19	uP_BUS_CLK	T4	GPMC_CLK/GPIO_59	O	1.8V	Processor bus clock. Frequency varies based on software setup. **NOTE:** uP_BUS_CLK is only active on bus transactions; it does not run continuously. See TI's *AM/DM37x TRM* and datasheets for additional information.
20	MAIN_BATTERY	(See Schematic)	(See Schematic)	I	max 4.5V	External power source input. This signal should be driven directly by a single cell lithium-ion battery or a fixed regulated power source.
21	uP_nBE1	U3	GPMC_nBE1/GPIO_61	O	1.8V	Processor bus Byte Lane Enable 1 bits [15:8].
22	DGND	(See Schematic)	(See Schematic)	I	GND	Ground. Connect to digital ground.
23	uP_nADV_ALE	F3	GPMC_nADV_ALE	O	1.8V	Processor GPMC address valid or address latch enable signal. (See notes 1 & 2)
24	BACKUP_BATT	M14 (PMIC)	BKBAT (PMIC)	I	1.8V-3.3V	External input that supplies power to the onboard power-management controller and RTC interface. This signal should be powered by a coin-cell type battery or an always-on power source.
25	uP_nBE0	G3	GPMC_nBE0_CLE/ GPIO_60	O	1.8V	Processor bus Byte Lane Enable 0 bits [7:0]. (See notes 1 & 2)
26	uP_nWAIT	M8	GPMC_WAIT0	I	1.8V	Active low. Processor bus GPMC_WAIT0 signal. Used to extend bus transactions beyond programmed wait states. The external device signals completion of the cycle by deasserting the uP_nWAIT signal. This signal is connected to the PoP NAND flash R/B signal. (See notes 1 & 2)
27	DGND	(See Schematic)	(See Schematic)	I	GND	Ground. Connect to digital ground.

J1 Pin#	Signal Name	BGA Ball#	Processor Signal	I/O	Voltage	Description
28	uP_nCS6	P8	GPMC_nCS6/ SYS_nDMAREQ3/ McBSP4_DX/ GPT11_PWM_EVT/ GPIO_57	O	1.8V	External chip select available for customer use.
29	uP_D8	H2	GPMC_D8/GPIO_44	I/O	1.8V	Processor GPMC bus data bit 8. (See notes 1 & 2)
30	uP_DREQ0	J8 AG11	GPMC_WAIT3/ SYS_nDMAREQ1/ UART4_RX/GPIO_65 POP_INT0_FT	I	1.8V	DMA Request signal for DMA4. Connected to SYS_nDMAREQ1 of the DM3730/AM3703. **NOTE:** This signal is shared with the PoP NAND chip's LOCK pin. This signal should be left floating at power-on to avoid conflict. (See notes 1 & 2)
31	uP_D9	K2	GPMC_D9/GPIO_45	I/O	1.8V	Processor GPMC bus data bit 9. (See notes 1 & 2)
32	uP_nCS5	R8	GPMC_nCS5/ SYS_nDMAREQ2/ McBSP4_DR/ GPT10_PWM_EVT/ GPIO_56	O	1.8V	External chip select available for customer use.
33	uP_D2	L2	GPMC_D2	I/O	1.8V	Processor GPMC bus data bit 2. (See notes 1 & 2)
34	uP_nCS4	T8	GPMC_nCS4/ SYS_nDMAREQ1/ McBSP4_CLKX/ GPT9_PWM_EVT/ GPIO_55	O	1.8V	External chip select available for customer use.
35	uP_D0	K1	GPMC_D0	I/O	1.8V	Processor GPMC bus data bit 0. (See notes 1 & 2)
36	uP_nCS3	U8	GPMC_nCS3/ SYS_nDMAREQ0/ GPIO_54	O	1.8V	External chip select available for customer use.
37	uP_D1	L1	GPMC_D1	I/O	1.8V	Processor GPMC bus data bit 1. (See notes 1 & 2)
38	uP_A10	K3	GPMC_A10/ SYS_nDMAREQ3/ GPIO_43	O	1.8V	Processor GPMC bus address bit 10.
39	uP_D3	P2	GPMC_D3	I/O	1.8V	Processor GPMC bus data bit 3. (See notes 1 & 2)
40	uP_nCS2	V8	GPMC_nCS2/GPIO_53	O	1.8V	External chip select available for customer use.
41	uP_D12	R2	GPMC_D12/GPIO_48	I/O	1.8V	Processor GPMC bus data bit 12. (See notes 1 & 2)
42	uP_A4	K4	GPMC_A4/GPIO_37	O	1.8V	Processor GPMC bus address bit 4.
43	uP_D10	P1	GPMC_D10/GPIO_46	I/O	1.8V	Processor GPMC bus data bit 10. (See notes 1 & 2)
44	uP_A3	L4	GPMC_A3/GPIO_36	O	1.8V	Processor GPMC bus address bit 3.
45	uP_D11	R1	GPMC_D11/GPIO_47	I/O	1.8V	Processor GPMC bus data bit 11. (See notes 1 & 2)

J1 Pin#	Signal Name	BGA Ball#	Processor Signal	I/O	Voltage	Description
46	uP_A2	M4	GPMC_A2/GPIO_35	O	1.8V	Processor GPMC bus address bit 2.
47	uP_D13	T2	GPMC_D13/GPIO_49	I/O	1.8V	Processor GPMC bus data bit 13. (See notes 1 & 2)
48	uP_A1	N4	GPMC_A1/GPIO_34	O	1.8V	Processor GPMC bus address bit 1.
49	uP_D4	T1	GPMC_D4	I/O	1.8V	Processor GPMC bus data bit 4. (See notes 1 & 2)
50	uP_A7	N3	GPMC_A7/GPIO_40	O	1.8V	Processor GPMC bus address bit 7.
51	MCSPI2_CS1	V3	McSPI2_CS1/ GPT8_PWM_EVT/ HSUSB2_TLL_DATA3/ USUSB2_DATA3/ MM2_TXEN_N/ GPIO_182	O	1.8V	McSPI2 interface chip select 1 output.
52	uP_A6	R3	GPMC_A6/GPIO_39	O	1.8V	Processor GPMC bus address bit 6.
53	uP_D6	V2	GPMC_D6	I/O	1.8V	Processor GPMC bus data bit 6. (See notes 1 & 2)
54	uP_A5	T3	GPMC_A5/GPIO_38	O	1.8V	Processor GPMC bus address bit 5.
55	uP_D7	W2	GPMC_D7	I/O	1.8V	Processor GPMC bus data bit 7. (See notes 1 & 2)
56	MCSPI2_SOMI	Y3	McSPI2_SOMI/ GPT10_PWM_EVT/ HSUSB2_TLL_DATA5/ HSUSB2_DATA5/ GPIO_180	I	1.8V	McSPI2 interface receive input.
57	uP_D5	V1	GPMC_D5	I/O	1.8V	Processor GPMC bus data bit 5. (See notes 1 & 2)
58	MCSPI2_CS0	Y4	McSPI2_CS0/ GPT11_PWM_EVT/ HSUSB2_TLL_DATA6/ HSUSB2_DATA6/ GPIO_181	O	1.8V	McSPI2 interface chip select 0 output.
59	uP_D14	W1	GPMC_D14/GPIO_50	I/O	1.8V	Processor GPMC bus data bit 14. (See notes 1 & 2)
60	MCSPI1_SOMI	AA4	McSPI1_SOMI/ MMC2_DAT6/GPIO_173	I	1.8V	McSPI1 interface receive input.
61	DGND	(See Schematic)	(See Schematic)	I	GND	Ground. Connect to digital ground.
62	MCBSP4_DR	AD1	McBSP4_DR/ SSI1_FLAG_RX/ HSUSB3_TLL_DATA0/ MM3_RXRCV/ GPIO_153	I	1.8V	McBSP4 interface receive input.
63	uP_D15	Y1	GPMC_D15/GPIO_51	I/O	1.8V	Processor GPMC bus data bit 15. (See notes 1 & 2)

J1 Pin#	Signal Name	BGA Ball#	Processor Signal	I/O	Voltage	Description
64	MCSPI1_CLK	AB3	McSPI1_CLK/ MMC2_DAT4GPIO_171	O	1.8V	McSPI1 serial clock signal.
65	MCSPI2_SIMO	Y2	McSPI2_SIMO/ GPT9_PWM_EVT/ HSUSB2_TLL_DATA4/ HSUSB2_DATA4/ GPIO_179	O	1.8V	McSPI2 interface transmit output.
66	MCSPI1_SIMO	AB4	McSPI1_SIMO/ MMC2_DAT5/GPIO_172	O	1.8V	McSPI1 interface transmit output.
67	MCSPI2_CLK	AA3	McSPI2_CLK/ HSUSB2_TLL_DATA7/ HSUSB2_DATA7/ GPIO_178	O	1.8V	McSPI2 serial clock signal.
68	uP_UARTA_CTS	W8	UART1_CTS/ SSI1_RDY_TX/ HSUSB3_TLL_CLK/ GPIO_150	I	1.8V	Clear To Send signal for UART1.
69	MCSPI1_CS1	AC3	McSPI1_CS1/ ADPLLV2D_DITHERING_EN2/ MMC3_CMD/GPIO_175	O	1.8V	McSPI1 interface chip select 1 output.
70	uP_UARTA_RX	Y8	UART1_RX/ MCBSP1_CLKR/ MCSPI4_CLK/ GPIO_151	I	1.8V	Data Receive signal for UART1.
71	MCSPI1_CS0	AC2	McSPI1_CS0/ MMC2_DAT7/GPIO_174	O	1.8V	McSPI1 interface chip select 0 output.
72	uP_UARTA_TX	AA8	UART1_TX/ SSI1_DAT_TX/ GPIO_148	O	1.8V	Data Transmit signal for UART1.
73	LCD_PANEL_PWR	AC1	McBSP4_FSX/ SSI1_WAKE/ HSUSB3_TLL_DATA3/ MM3_TXEN_n/ GPIO_155	O	1.8V	LCD Panel Power signal.
74	uP_UARTA_RTS	AA9	UART1_RTS/ SSI1_FLAG_TX/ GPIO_149	O	1.8V	Ready To Send signal for UART1.
75	LCD_BACKLIGHT_PWR	AD2	McBSP4_DX/ SSI1_RDY_RX// HSUSB3_TLL_DATA2/ MM3_TXDAT/GPIO_154	O	1.8V	LCD Backlight Power signal. Active High.
76	R90 Populated **(default)**: ADCIN0 (CONFIG11)	H4 (PMIC)	ADCIN0 (PMIC)	I	max 1.5V	Analog to digital converter input. Connected to TPS65950 ADCIN0. Tie to DGND when not used.
	R91 Populated: CSI_D8 (CONFIG11)	K27 (PMIC)	CAM_D8/GPIO_107	I	1.8V	Camera Sensor Interface Data bit 8. This signal may also be used as GPI; output signaling is not supported.

J1 Pin#	Signal Name	BGA Ball#	Processor Signal	I/O	Voltage	Description
77	MCBSP3_DR	T15 (PMIC) AE6	PCM.VDX (PMIC) McBSP3_DR/UART2_RTS/HSUSB3_TLL_DATA5/GPIO_141	I	1.8V	McBSP3 interface receive input.
78	R90 Populated **(default)**: ADCIN1 (CONFIG10)	J3 (PMIC)	ADCIN1 (PMIC)	I	max 1.5V	Analog to digital converter input. Connected to TPS65950 ADCIN1. Tie to DGND when not used.
	R91 Populated: CSI_D9 (CONFIG10)	L27	CAM_D9/GPIO_108	I	1.8V	Camera Sensor Interface Data bit 9. This signal may also be used as GPI; output signaling is not supported.
79	MCBSP3_DX	T2 (PMIC) AF6	PCM.VDR (PMIC) McBSP3_DX/ UART21_CTS/ HSUSB3_TLL_DATA4/ GPIO_140	O	1.8V	McBSP3 interface transmit output.
80	R90 Populated **(default)**: ADCIN2 (CONFIG9)	G3 (PMIC)	ADCIN2 (PMIC)	I	max 2.5V	Analog to digital converter input. Connected to TPS65950 ADCIN2. Tie to DGND when not used.
	R91 Populated: CSI_D10 (CONFIG9)	B25	CAM_D10/SSI2_WAKE/ GPIO_109	I	1.8V	Camera Sensor Interface Data bit 10.
81	MCBSP3_FSX	R16 (PMIC) AE5	PCM.VFS (PMIC) McBSP3_FSX/ UART2_RX/ HSUSB3_TLL_DATA7/ GPIO_143	I/O	1.8V	McBSP3 transmit frame synchronization. **NOTE:** This signal is also connected to the wireless module D7002.
82	R90 Populated **(default)**: ADCIN3 (CONFIG8)	P11 (PMIC)	ADCIN3 (PMIC)	I	max 2.5V	Analog to digital converter input. Connected to TPS65950 ADCIN3. Tie to DGND when not used.
	R91 Populated: CSI_D11 (CONFIG8)	C26	CAM_D11/GPIO_110	I	1.8V	Camera Sensor Interface Data bit 11.
83	MCBSP3_CLKX	R1 (PMIC) AF5	PCM.VCK (PMIC) McBSP3_CLKX/ UART2_TX/ HSUSB3_TLL_DATA6/ GPIO_142	O	1.8V	McBSP3 transmit clock output. **NOTE:** This signal is also connected to the wireless module D7002.
84	SD2_DATA0	AH5	MMC2_DAT0/ McSPI3_SOMI/ GPIO_132	I/O	1.8V	MMC/SD2 Data 0 signal. This signal requires a 10K pull-up to VIO_1V8.
85	DGND	(See Schematic)	(See Schematic)	I	GND	Ground. Connect to digital ground.
86	R86 Populated **(default)**: LCD_D17 (CONFIG1)	H27	DSS_D17/GPIO_87	O	1.8V	LCD data bit when operating in 24 bpp color mode. Please see the *AM/DM37x TRM* for LCD bus mapping.
	R87 Populated: MCSPI1_CS2 (CONFIG1)	AB1	McSPI1_CS2/ MMC3_CLK/ GPIO_176	O	1.8V	McSPI1 interface chip select 2 output.

J1 Pin#	Signal Name	BGA Ball#	Processor Signal	I/O	Voltage	Description
87	LCD_D23	AF21	SYS_BOOT6/DSS_D23 /GPIO_8	O	1.8V	LCD data bit when operating in 24 bpp color mode. Please see the *AM/DM37x TRM* for LCD bus mapping. Must be left floating during boot-up, unless the boot order is to be modified. This signal has a 4.7K pull-up on the SOM.
88	R86 Populated **(default)**: MCSPI3_CLK (CONFIG3)	AE13	ETK_D3/McSPI3_CLK/ MMC3_DAT3/ HSUSB1_DATA7/ HSUSB1_TLL_DATA7/ GPIO_17	O	1.8V	McSPI3 serial clock signal. **NOTE:** Used by software to control audio mute circuit on Torpedo Launcher 3 Baseboard. If you wish to use as a GPIO or SPI CLK, contact Logic PD for information about how to modify source code.
	R87 Populated: MCSPI1_CS3 (CONFIG3)	AB2	McSPI1_CS3/ HSUSB2_TLL_DATA2/ MM2_TXDAT/GPIO_17 7	O	1.8V	McSPI1 interface chip select 3 output.
89	SD2_CLK	AE2	MMC2_CLK/ McSPI3_CLK/GPIO_13 0	O	1.8V	MMC/SD2 Clock signal.
90	MCSPI3_SOMI	AE3	MMC2_DAT7/ MMC2_CLKIN/ MMC3_DAT3/ HSUSB3_TLL_NXT/ MM3_RXDM/GPIO_139	I	1.8V	MMC/SD3 Data 3 signal. This signal requires a 10K pull-up to VIO_1V8.
91	SD2_DATA3	AF4	MMC2_DAT3/ McSPI3_CS0/GPIO_13 5	I/O	1.8V	MMC/SD2 Data 3 signal. This signal requires a 10K pull-up to VIO_1V8.
92	MCSPI3_SIMO	AF3	MMC2_DAT6/ MMC2_DIR_CMD/ CAM_SHUTTER/ MMC3_DAT2/ HSUSB3_TLL_DIR/ GPIO_138	O	1.8V	MMC/SD3 Data 2 signal. This signal requires a 10K pull-up to VIO_1V8.
93	SD2_DATA2	AG4	MMC2_DAT2/ McSPI3_CS1/GPIO_13 4	I/O	1.8V	MMC/SD2 Data 2 signal. This signal requires a 10K pull-up to VIO_1V8.
94	MCSPI3_CS0	AH3	MMC2_DAT5/ MMC2_DIR_DAT1/ CAM_GLOBAL_RESET / MMC3_DAT1/ HSUSB3_TLL_STP/ MM3_RXDP/GPIO_137	O	1.8V	MMC/SD3 Data 1 signal. This signal requires a 10K pull-up to VIO_1V8.
95	SD2_DATA1	AH4	MMC2_DAT1/GPIO_13 3	I/O	1.8V	MMC/SD2 Data 1 signal. This signal requires a 10K pull-up to VIO_1V8.
96	MCSPI3_CS1	AH14	ETK_D7/McSPI3_CS1/ MMC3_DAT7/ HSUSB1_DATA3/ MM1_TXEN_n/ HSUSB1_TLL_DATA3/ GPIO_21	O	1.8V	McSPI3 interface chip select 1 output.

J1 Pin#	Signal Name	BGA Ball#	Processor Signal	I/O	Voltage	Description
97	SD2_CMD	AG5	MMC2_CMD/ McSPI3_SIMO/ GPIO_131	I/O	1.8V	MMC/SD2 Command signal. This signal requires a 10K pull-up to VIO_1V8.
98	uP_IODIR	N8	GPMC_nCS7/ GPMC_IODIR/ McBSP4_FSX/ GPT8_PWM_EVT/ GPIO_58	O	1.8V	When high, external buffers should drive data from external devices towards the Torpedo + Wireless SOM (Torpedo + Wireless SOM is reading). When low, external buffers should drive data from the Torpedo + Wireless SOM towards external devices (Torpedo + Wireless SOM is writing).
99	LCD_D16	G25	DSS_D16/GPIO_86	O	1.8V	LCD data bit when operating in 24 bpp color mode. Please see the *AM/DM37x TRM* for LCD bus mapping.
100	DGND	(See Schematic)	(See Schematic)	I	GND	Ground. Connect to digital ground.

TABLE NOTES:

1. Use caution when considering these signals for alternative functions as they may connect to the top package-on-package BGA footprint.
2. When using package-on-package memories with 16-bit NAND memory, these signals present an additional load on the GPMC bus that must be accounted for when calculating overall bus load.

7.2 J2 Connector 100-Pin Descriptions

J2 Pin#	Signal Name	Ball BGA #	Processor Signal	I/O	Voltage	Description
1	DGND	(See Schematic)	(See Schematic)	I	GND	Ground. Connect to digital ground.
2	DGND	(See Schematic)	(See Schematic)	I	GND	Ground. Connect to digital ground.
3	USB1_D+	T10 (PMIC)	DP/UART3.RXD (PMIC)	I/O	Variable (see note 1)	USB OTG port 1 I/O data plus signal. Route as differential pair with USB1_D-. Follow USB 2.0 routing guidelines. Route pair with 90 ohms differential impedance.
4	VIO_1V8	(See Schematic)	(See Schematic)	O	1.8V	Voltage reference output created on Torpedo + Wireless SOM.
5	USB1_D-	T11 (PMIC)	DN/UART3.TXD (PMIC)	I/O	Variable (see note 1)	USB OTG port 1 I/O data minus signal. Route as differential pair with USB1_D+. Follow USB 2.0 routing guidelines. Route pair with 90 ohms differential impedance.

J2 Pin#	Signal Name	Ball BGA #	Processor Signal	I/O	Voltage	Description
6	SYS_nRESWARM	AG13 AF24 B13 (PMIC)	POP_RESET_RP_FT SYS_nRESWARM/ GPIO_30 NRESWARM (PMIC)	O	1.8V	Active low. Reset output from the CPU that drives all onboard reset inputs. This signal should be used to drive reset inputs on external chips that require similar timing to the onboard devices. The SYS_nRESWARM signal has a 4.7K pull up to VIO_1V8.
7	VIO_1V8	(See Schematic)	(See Schematic)	O	1.8V	Voltage reference output created on Torpedo + Wireless SOM.
8	BT_PCM_DR	C3 (PMIC)	GPIO.16/BT.PCMVDR/ DIG.MIC.CLK0 (PMIC)	I	1.8V	Bluetooth PCM receive data. This signal is connected to the wireless module D7002 and should not be used elsewhere.
9	USB1_ID	R11 (PMIC)	ID (PMIC)	I/O	5.0V	Tie to pin 4 of a USB 2.0 OTG compliant connector. This signal negotiates host/device operation with an external USB product. See Torpedo Launcher 3 Baseboard design for reference components.
10	BT_PCM_DX	C5 (PMIC)	GPIO.17/BT.PCM.VDX / DIG.MIC.CLK1 (PMIC)	O	1.8V	Bluetooth PCM transmit data. This signal is connected to the wireless module D7002 and should not be used elsewhere.
11	USB1_VBUS	R8 (PMIC)	VBUS (PMIC)	I/O	5.0V	Ties to pin 1 of a USB 2.0 OTG compliant connector. This signal indicates to the USB controller that an external USB Host has been connected or can provide power to USB Device peripherals. See Torpedo Launcher 3 Baseboard design for reference components.
12	LCD_HSYNC	D26	DSS_HSYNC/GPIO_6 7	O	1.8V	LCD Horizontal Sync signal.
13	USB1_VBUS	R8 (PMIC)	VBUS (PMIC)	I/O	5.0V	Ties to pin 1 of a USB 2.0 OTG compliant connector. This signal indicates to the USB controller that an external USB Host has been connected or can provide power to USB Device peripherals. See Torpedo Launcher 3 Baseboard design for reference components.
14	LCD_VSYNC	D27	DSS_VSYNC/GPIO_6 8	O	1.8V	LCD Vertical Sync Signal.
15	TWL_32K_CLK_OUT	N10 (PMIC) AE25	32KCLKOUT (PMIC) 32KCLKOUT	O	1.8V	TPS65950 PMIC 32 kHz clock output.
16	LCD_MDISP	E27	DSS_ACBIAS/GPIO_6 9	O	1.8V	LCD MDISP signal.
17	T2_REGEN	A10 (PMIC)	REGEN (PMIC)	O	Max 4.5V (MAIN_BATTERY)	Active high, open-drain. External LDO enable signal generated by the TPS65950. This signal has an internal pull-up in the TPS65950.

J2 Pin#	Signal Name	Ball BGA #	Processor Signal	I/O	Voltage	Description
18	LCD_D6 (G1)	E26	DSS_D6/UART1_TX/ GPIO_76	O	1.8V	LCD G1 data bit when operating in 16 bpp 5:6:5 color mode. Please see the *AM/DM37x TRM* for 24-bit LCD bus mapping.
19	CSI2_DX0_R	AG19	CSI2_DX0/GPIO_112	I	1.8V (VAUX4) (see note 3)	MIPI CSI2 DX0 input. Connected through 0 ohm series resistor that is not populated by default. Route as differential pair with CSI2_DY0_R. Route pair with 100 ohms differential impedance. (See note 4 & 7)
20	LCD_D20 (SYS_BOOT3)	AF18	SYS_BOOT3/ DSS_D20/GPIO_5	O	1.8V	LCD data bit when operating in 24 bpp color mode. Please see the *AM/DM37x TRM* for LCD bus mapping. Must be left floating during boot-up, unless the boot order is to be modified. This signal has a 4.7K pull-up on the SOM.
21	CSI2_DY0_R	AH19	CSI2_DY0/GPIO_113	I	1.8V (VAUX4) (see note 3)	MIPI CSI2 DY0 input. Connected through 0 ohm series resistor that is not populated by default. Route as differential pair with CSI2_DX0_R. Route pair with 100 ohms differential impedance. (See note 4 & 7)
22	LCD_D9 (G4)	G26	DSS_D9/ UART3_TX_IRTX/ GPIO_79	O	1.8V	LCD G4 data bit when operating in 16 bpp 5:6:5 color mode. Please see the *AM/DM37x TRM* for 24-bit LCD bus mapping.
23	CSI2_DX1_R	AG18	CSI2_DX1/GPIO_114	I	1.8V (VAUX4) (see note 3)	MIPI CSI2 DX1 input. Connected through 0 ohm series resistor that is not populated by default. Route as differential pair with CSI2_DY1_R. Route pair with 100 ohms differential impedance. (See note 4 & 7)
24	LCD_D8 (G3)	F27	DSS_D8/ UART3_RX_IRRX/ GPIO_78	O	1.8V	LCD G3 data bit when operating in 16 bpp 5:6:5 color mode. Please see the *AM/DM37x TRM* for 24-bit LCD bus mapping.
25	CSI2_DY1_R	AH18	CSI2_DY1/GPIO_115	I	1.8V (VAUX4) (see note 3)	MIPI CSI2 DY1 input. Connected through 0 ohm series resistor that is not populated by default. Route as differential pair with CSI2_DX1_R. Route pair with 100 ohms differential impedance. (See note 4 & 7)
26	LCD_D7 (G2)	F28	DSS_D7/UART1_RX/ GPIO_77	O	1.8V	LCD G2 data bit when operating in 16 bpp 5:6:5 color mode. Please see the *AM/DM37x TRM* for 24-bit LCD bus mapping.
27	DGND	(See schematic)	(See schematic)	I	GND	Ground. Connect to digital ground.
28	LCD_DCLK	D28	DSS_PCLK/GPIO_66	O	1.8V	LCD Data Clock output.

J2 Pin#	Signal Name	Ball BGA #	Processor Signal	I/O	Voltage	Description
29	CSI_D5	A25	CAM_D5/ SSI2_RDY_RX/ GPIO_104	I	1.8V	Camera Sensor Interface Data bit 5.
30	DGND	(See schematic)	(See schematic)	I	GND	Ground. Connect to digital ground.
31	CSI_D2	B24	CAM_D2/ SSI2_RDY_TX/ GPIO_101	I	1.8V	Camera Sensor Interface Data bit 2.
32	SD1_CLK	N28	MMC1_CLK/MS_CLK/ GPIO_120	O	3.0V (VMMC1)	MMC/SD1 Clock signal.
33	CSI_D3	C24	CAM_D3/ SSI2_DAT_RX/ GPIO_102	I	1.8V	Camera Sensor Interface Data bit 3.
34	LCD_D19 (SYS_BOOT1)	AG26	SYS_BOOT1/ DSS_D19/GPIO_3	O	1.8V	LCD data bit when operating in 24 bpp color mode. Please see the *AM/DM37x TRM* for LCD bus mapping. Must be left floating during boot-up, unless the boot order is to be modified. This signal has a 4.7K pull-up on the SOM.
35	CSI_D4	D24	CAM_D4/ SSI2_FLAG_RX/ GPIO_103	I	1.8V	Camera Sensor Interface Data bit 4.
36	LCD_D18 (SYS_BOOT0)	AH26	SYS_BOOT0/ DSS_D18/GPIO_2	O	1.8V	LCD data bit when operating in 24 bpp color mode. Please see the *AM/DM37x TRM* for LCD bus mapping. Must be left floating during boot-up, unless the boot order is to be modified. This signal has a 4.7K pull-up on the SOM. This signal is also connected to J2 pin 100.
37	uP_UARTB_CTS	H18	UART3_CTS_RCTX/ GPIO_163	I	1.8V	Clear To Send signal for UART3.
38	BATT_LINE	J25	HDQ_SIO/ SYS_ALTCLK/ I2C2_SCCBE/ I2C3_SCCBE/ GPIO_170	I/O	1.8V	Bi-directional battery management ONEWIRE interface. This signal has a 4.7K pull-up to VIO_1V8.
39	uP_UARTB_RTS	H19	UART3_RTS_SD/ GPIO_164	O	1.8V	Ready To Send signal for UART3.
40	LCD_D21 (SYS_BOOT4)	AF19	SYS_BOOT4/ MMC2_DIR_DAT2/ DSS_D21/GPIO_6	O	1.8V	LCD data bit when operating in 24 bpp color mode. Please see the *AM/DM37x TRM* for LCD bus mapping. Must be left floating during boot-up, unless the boot order is to be modified. This signal has a 4.7K pull-down on the SOM.
41	uP_UARTB_RX	H20	UART3_RX_IRRX/ GPIO_165	I	1.8V	Serial Data Receive signal for UART3.
42	SD1_CMD	M27	MMC1_CMD/MS_BS/ GPIO_121	I/O	3.0V (VMMC1)	MMC/SD1 Command signal. This signal requires a 10K pull-up to VMMC1.

J2 Pin#	Signal Name	Ball BGA #	Processor Signal	I/O	Voltage	Description
43	uP_UARTB_TX	H21	UART3_TX_IRTX/ GPIO_166	O	1.8V	Serial Data Transmit signal for UART3.
44	SD1_DATA2	N25	MMC1_DAT2/ MS_DAT2/GPIO_124	I/O	3.0V (VMMC1)	MMC/SD1 Data 2 signal. This signal requires a 10K pull-up to VMMC1.
45	MCSPI4_CS0	K26	McBSP1_FSX/ McSPI4_CS0/ McBSP_FSX/ GPIO_161	O	1.8V	McSPI4 interface chip select 0 output.
46	SD1_DATA1	N26	MMC1_DAT1/ MS_DAT1/GPIO_123	I/O	3.0V (VMMC1)	MMC/SD1 Data 1 signal. This signal requires a 10K pull-up to VMMC1.
47	MCBSP2_DX	K4 (PMIC) M21	I2S.DIN/TDM.DIN (PMIC) McBSP2_DX/ GPIO_119	O	1.8V	McBSP2 interface transmit output.
48	SD1_DATA0	N27	MMC1_DAT0/ MS_DAT0/GPIO_122	I/O	3.0V (VMMC1)	MMC/SD1 Data 0 signal. This signal requires a 10K pull-up to VMMC1.
49	MCBSP2_CLKX	L3 (PMIC) N21	I2S.CLK/TDM.CLK (PMIC) McBSP2_CLKX/ GPIO_117	O	1.8V	McBSP2 transmit clock output.
50	SD1_DATA3	P28	MMC1_DAT3/ MS_DAT3/GPIO_125	I/O	3.0V (VMMC1)	MMC/SD1 Data 3 signal. This signal requires a 10K pull-up to VMMC1.
51	MCBSP2_FSX	K6 (PMIC) P21	I2S.SYNC/TDM.SYNC (PMIC) McBSP2_FSX/ GPIO_116	I/O	1.8V	McBSP2 transmit frame synchronization.
52	CSI_FLD	C23	CAM_FLD/ CAM_GLOBAL_RESET/GPIO_98	I/O	1.8V	Camera Sensor Interface field identification.
53	MCBSP2_DR	K3 (PMIC) R21	I2S.DOUT/TDM.DOUT (PMIC) McBSP2_DR/ GPIO_118	I	1.8V	McBSP2 interface receive input.
54	uP_GPIO_127	P26	SIM_CLK/GPIO_127	I/O	1.8V	Processor GPIO 127. (See note 2)
	R92 Populated: KEY_ROW3 (CONFIG15)	K7 (PMIC)	KPD.R3 (PMIC)	I	1.8V	Keypad Row 3 signal.
55	R93 Populated **(default)**: CSI_D7 (CONFIG15)	L28	CAM_D7/GPIO_106	I	1.8V	Camera Sensor Interface Data bit 7. This signal may also be used as GPI; output signaling is not supported.
56	uP_GPIO_128	R27	SIM_PWRCTRL/ GPIO_128	I/O	1.8V	Processor GPIO 128.
57	R92 Populated: KEY_ROW2 (CONFIG14)	L8 (PMIC)	KPD.R2 (PMIC)	I	1.8V	Keypad Row 2 signal.

J2 Pin#	Signal Name	Ball BGA #	Processor Signal	I/O	Voltage	Description
	R93 Populated **(default)**: CSI_D6 (CONFIG14)	K28	CAM_D6/GPIO_105	I	1.8V	Camera Sensor Interface Data bit 6. This signal may also be used as GPI; output signaling is not supported.
58	uP_GPIO_129	R25	SIM_RST/GPIO_129	I/O	1.8V	Processor GPIO 129.
59	DGND	(See schematic)	(See schematic)	I	GND	Ground. Connect to digital ground.
60	GPS_PPS_OUT	--	--	O	1.8V	GPS pulse per second output.
61	R92 Populated: KEY_ROW1 (CONFIG13)	K8 (PMIC)	KPD.R1 (PMIC)	I	1.8V	Keypad Row 1 signal.
	R93 Populated **(default)**: CAM_WEN (CONFIG13)	B23	CAM_WEN/ CAM_SHUTTER/ GPIO_167	I	1.8V	Camera Sensor Write Enable.
62	DGND	(See schematic)	(See schematic)	I	GND	Ground. Connect to digital ground.
63	R92 Populated: KEY_ROW0 (CONFIG12)	K9 (PMIC)	KPD.R0 (PMIC)	I	1.8V	Keypad Row 0 signal.
	R93 Populated **(default)**: CSI_HSYNC (CONFIG12)	A24	CAM_HS/ SSI2_DAT_TX/ GPIO_94	I/O	1.8V	Camera Sensor Interface Horizontal Sync signal.
64	BT_EN	W21	McBSP1_CLKX/McBSP3_CLKX/GPIO_162	I	1.8V	Active high. Bluetooth enable signal. This signal is normally controlled by the processor. It may be provided off the SOM when the processor is in a low-power state to wake up the Bluetooth/GPS device.
65	R94 populated: KEY_COL3 (CONFIG19)	F7 (PMIC)	KPD.C3 (PMIC)	O	1.8V	Keypad Column 3 signal.
	R95 Populated **(default)**: CSI_VSYNC (CONFIG19)	A23	CAM_VS/ SSI2_FLAG_TX/ GPIO_95	I/O	1.8V	Camera Sensor Interface Vertical Sync signal.
66	LCD_D14 (R4)	AA28	DSS_D14/SDI_DAT3N / GPIO_84	O	1.8V	LCD R4 data bit when operating in 16 bpp 5:6:5 color mode. Please see the *AM/DM37x TRM* for 24-bit LCD bus mapping.
67	R94 Populated: KEY_COL2 (CONFIG18)	G6 (PMIC)	KPD.C2 (PMIC)	O	1.8V	Keypad Column 2 signal.
	R95 Populated **(default)**: CSI_PCLK (CONFIG18)	C27	CAM_PCLK_GPIO_97	I	1.8V	Camera Sensor Interface Pixel Clock signal.
68	LCD_D13 (R3)	AB27	DSS_D13/SDI_DAT2P/ GPIO_83	O	1.8V	LCD R3 data bit when operating in 16 bpp 5:6:5 color mode. Please see the *AM/DM37x TRM* for 24-bit LCD bus mapping.
69	R94 Populated: KEY_COL1 (CONFIG17)	H7 (PMIC)	KPD.C1 (PMIC)	O	1.8V	Keypad Column 1 signal.
	R95 Populated **(default)**: CSI_XCLKB (CONFIG17)	B26	CAM_XCLKB/ GPIO_111	O	1.8V	Camera Sensor Clock Output b.

J2 Pin#	Signal Name	Ball BGA #	Processor Signal	I/O	Voltage	Description
70	LCD_D12 (R2)	AB28	DSS_D12/SDI_DAT2N / GPIO_82	O	1.8V	LCD R2 data bit when operating in 16 bpp 5:6:5 color mode. Please see the *AM/DM37x TRM* for 24-bit LCD bus mapping.
71	R94 Populated: KEY_COL0 (CONFIG16)	G8 (PMIC)	KPD.C0 (PMIC)	O	1.8V	Keypad Column 0 signal.
	R95 Populated **(default)**: CSI_XCLKA (CONFIG16)	C25	CAM_XCLKA/GPIO_96	O	1.8V	Camera Sensor Clock Output a.
72	uP_UARTC_TX	AA25	UART2_TX/ MCBSP3_CLKX/ GPT11_PWM_EVT/ GPIO_146	O	1.8V	Serial Data Transmit signal for UART2. **NOTE:** This signal is connected to the wireless module D7002 and should only be used for communication to the wireless module when the processor is in a sleep mode. Leave unconnected if not used.
73	R88 Populated: MCBSP5_DX (CONFIG7)	AF13	ETK_D6/McBSP5_DX/ MMC3_DAT2/ HSUSB1_DATA6/ HSUSB1_TLL_DATA6/ GPIO_20	O	1.8V	McBSP5 interface transmit output.
	R89 Populated **(default)**: MCSPI4_SOMI (CONFIG7)	U21	McBSP1_DR/ McSPI4_SOMI/ McBSP3_DR/ GPIO_159	I	1.8V	McSPI4 interface receive input.
74	uP_UARTC_RTS	AB25	UART2_RTS/ MCBSP3_DR/ GPT10_PWM_EVT/ GPIO_145	O	1.8V	Ready To Send signal for UART2. **NOTE:** This signal is connected to the wireless module D7002 and should only be used for communication to the wireless module when the processor is in a sleep mode. Leave unconnected if not used.
75	R88 Populated: MCBSP5_FSX (CONFIG6)	AH9	ETK_D5/McBSP5_FSX / MMC3_DAT1/ HSUSB1_DATA5/ HSUSB1_TLL_DATA5/ GPIO_19	I/O	1.8V	McBSP5 transmit frame synchronization.
	R89 Populated **(default)**: MCSPI4_SIMO (CONFIG6)	V21	McBSP1_DX/ McSPI4_SIMO/ McBSP3_DX/ GPIO_158	O	1.8V	McSPI4 interface transmit output.
76	uP_UARTC_CTS	AB26	UART2_CTS/ MCBSP3_DX/ GPT9_PWM_EVT/ GPIO_144	I	1.8V	Clear To Send signal for UART2. **NOTE:** This signal is connected to the wireless module D7002 and should only be used for communication to the wireless module when the processor is in a sleep mode. Leave unconnected if not used.

J2 Pin#	Signal Name	Ball BGA #	Processor Signal	I/O	Voltage	Description
77	R88 Populated: MCBSP5_DR (CONFIG5)	AE11	ETK_D4/McBSP5_DR/ MMC3_DAT0/ HSUSB1_DATA4/ HSUSB1_TLL_DATA4/ GPIO_18	I	1.8V	McBSP5 interface receive input.
	R89 Populated **(default)**: MCSPI4_CLK (CONFIG5)	Y21	McBSP1_CLKR/ McSPI4_CLK/ SIM_CD/GPIO_156	O	1.8V	McSPI4 serial clock signal.
78	LCD_D15 (R5)	AA27	DSS_D15/SDI_DAT3P/ GPIO_85	O	1.8V	LCD R5 data bit when operating in 16 bpp 5:6:5 color mode. Please see the *AM/DM37x TRM* for 24-bit LCD bus mapping.
79	R143 Populated **(default)**: LCD_D2 (B3)(CONFIG20)	E28	DSS_D20/SDI_DEN/ McSPI3_SOMI/ DSS_D2/GPIO_90	O	1.8V	LCD B3 data bit when operating in 16 bpp 5:6:5 color mode. Please see the *AM/DM37x TRM* for 24-bit LCD bus mapping.
	R142 Populated: DSI_DX0 (CONFIG20)	AG22	DSS_D0/UART1_CTS/ DX0/GPIO_70	O	1.8V (VPLL2) (see note 5)	MIPI DSI DX0 output. Route as differential pair with DSI_DY0. Route pair with 100 ohms differential impedance. (See note 6)
80	LCD_D22 (SYS_BOOT5)	AE21	SYS_BOOT5/ MMC2_DIR_DAT3/ DSS_D22/GPIO_7	O	1.8V	LCD data bit when operating in 24 bpp color mode. Please see the *AM/DM37x TRM* for LCD bus mapping. Must be left floating during boot-up, unless the boot order is to be modified. This signal has a 4.7K pull-up on the SOM. This signal is also connected to pin J2.89.
81	R145 Populated **(default)**: LCD_D3 (B4)(CONFIG21)	J26	DSS_D21/SDI_STP/ McSPI3_CS0/ DSS_D3/GPIO_91	O	1.8V	LCD B4 data bit when operating in 16 bpp 5:6:5 color mode. Please see the *AM/DM37x TRM* for 24-bit LCD bus mapping.
	R144 Populated: DSI_DY0 (CONFIG21)	AH22	DSS_D1/UART1_RTS/ DY0/GPIO_71	O	1.8V (VPLL2) (see note 5)	MIPI DSI DY0 output. Route as differential pair with DSI_DX0. Route pair with 100 ohms differential impedance. (See note 6)
82	R138 Populated **(default)**: LCD_D10 (G5)(CONFIG24)	AD28	DSS_D10/SDI_DAT1N / GPIO_80	O	1.8V	LCD G5 data bit when operating in 16 bpp 5:6:5 color mode. Please see the *AM/DM37x TRM* for 24-bit LCD bus mapping.
	R139 Populated: DSI_DX2 (CONFIG24)	AG24	DSS_D4/UART3_RX_IRRX/DX2/GPIO_74	O	1.8V (VPLL2) (see note 5)	MIPI DSI DX2 output. Route as differential pair with DSI_DY2. Route pair with 100 ohms differential impedance. (See note 6)
83	LCD_D1 (B2)	H25	DSS_D19/SDI_HSYNC / McSPI3_SIMO/ DSS_D1/GPIO_89	O	1.8V	LCD B2 data bit when operating in 16 bpp 5:6:5 color mode. Please see the *AM/DM37x TRM* for 24-bit LCD bus mapping.

J2 Pin#	Signal Name	Ball BGA #	Processor Signal	I/O	Voltage	Description
84	R140 Populated **(default)**: LCD_D11 (R1)(CONFIG25)	AD27	DSS_D11/ SDI_DAT1P/GPIO_81	O	1.8V	LCD R1 data bit when operating in 16 bpp 5:6:5 color mode. Please see the *AM/DM37x TRM* for 24-bit LCD bus mapping.
	R141 Populated: DSI_DY2 (CONFIG25)	AH24	DSS_D5/UART3_TX_IRTX/DY2/GPIO_75	O	1.8V (VPLL2) (see note 5)	MIPI DSI DY2 output. Route as differential pair with DSI_DX2. Route pair with 100 ohms differential impedance. (See note 6)
85	CSI_D0	AG17	CAM_D0/CSI2_DX2/ GPIO_99	I	1.8V (VAUX4) (see note 3)	Camera Sensor Interface Data bit 0. This signal may also be used as GPI; output signaling is not supported. Route as differential pair with CSI_D1. Route pair with 100 ohms differential impedance. **NOTE:** The VAUX4 supply is off by default and must be enabled by software. (See note 7)
86	uP_UARTC_RX	AD25	UART2_RX/ MCBSP3_FSX/ GPT8_PWM_EVT/ GPIO_147	I	1.8V	Serial Data Receive signal for UART2. **NOTE:** This signal is connected to the wireless module D7002 and should only be used for communication to the wireless module when the processor is in a sleep mode. Leave unconnected if not used.
87	CSI_D1	AH17	CAM_D1/CSI2_DY2/ GPIO_100	I	1.8V (VAUX4) (see note 3)	Camera Sensor Interface Data bit 1. This signal may also be used as GPI; output signaling is not supported. Route as differential pair with CSI_D0. Route pair with 100 ohms differential impedance. **NOTE:** The VAUX4 supply is off by default and must be enabled by software. (See note 7)
88	uP_CLKOUT1_26MHz	AG25	SYS_CLKOUT1/ GPIO_10	O	1.8V	Processor SYS_CLKOUT1.
89	SYS_BOOT5 (LCD_D22)	AE21	SYS_BOOT5/ MMC2_DIR_DAT3/ DSS_D22/GPIO_7	I/O	1.8V	Processor SYS_BOOT5. Must be left floating during boot up, unless the boot order is to be modified. This signal has a 4.7K pull-up on the SOM. See Table 5.1 for more information. This signal is also connected to pin J2.80.
90	DGND	(See schematic)	(See schematic)	I	GND	Ground. Connect to digital ground.
91	uP_I2C2_SDA	AE15	I2C2_SDA/GPIO_183	I/O	1.8V	I2C channel 2 data signal. This signal has a 4.7K pull-up to the reference voltage onboard.
92	MSTR_nRST	AH25	SYS_nRESPWRON	I	1.8V	Active low. External reset input to the Torpedo + Wireless SOM. This signal should be used to reset devices on the Torpedo + Wireless SOM including the CPU. **NOTE:** This signal does not reset the TPS65950 PMIC; please see Section 5.2.1.

J2 Pin#	Signal Name	Ball BGA #	Processor Signal	I/O	Voltage	Description
93	uP_I2C2_SCL	AF15	I2C2_SCL/GPIO_168	I/O	1.8V	I2C channel 2 clock signal. This signal has a 4.7K pull-up to the reference voltage onboard.
94	R146 Populated: DSI_DX1 (CONFIG22)	AG23	DSS_D2/DX1/GPIO_72	O	1.8V (VPLL2) (see note 5)	MIPI DSI DX1 output. Route as differential pair with DSI_DY1. Route pair with 100 ohms differential impedance. (See note 6)
	R147 Populated **(Default)**: LCD_D4 (B5) (CONFIG22)	AC27	DSS_D22/SDI_CLKP/ McSPI3_CS1/DSS_D4/ GPIO_92	O	1.8V	LCD B5 data bit when operating in 16 bpp 5:6:5 color mode. Please see the *AM/DM37x TRM* for 24-bit LCD bus mapping.
95	uP_I2C3_SCL	AF14	I2C3_SCL/GPIO_184	I/O	1.8V	I2C channel 3 Clock signal. This signal has a 4.7K ohm pull-up on the SOM.
96	R148 Populated: DSI_DY1 (CONFIG23)	AH23	DSS_D3/DY1/GPIO_73	O	1.8V (VPLL2) (see note 5)	MIPI DSI DY1 output. Route as differential pair with DSI_DX1. Route pair with 100 ohms differential impedance. (See note 6)
	R149 Populated **(Default)**: LCD_D5 (G0) (CONFIG23)	AC28	DSS_D23/SDI_CLKN/ DSS_D5/GPIO_93	O	1.8V	LCD G0 data bit when operating in 16 bpp 5:6:5 color mode. Please see the *AM/DM37x TRM* for 24-bit LCD bus mapping.
97	uP_I2C3_SDA	AG14	I2C3_SDA/GPIO_185	I/O	1.8V	I2C channel 3 Data signal. This signal has a 4.7K ohm pull-up on the SOM.
98	LCD_D0 (B1)	H26	DSS_D18/SDI_VSYNC / McSPI3_CLK/DSS_D0/ GPIO_88	O	1.8V	LCD B1 data bit when operating in 16 bpp 5:6:5 color mode. Please see the *AM/DM37x TRM* for 24-bit LCD bus mapping.
99	DGND	(See schematic)	(See schematic)	I	GND	Ground. Connect to digital ground.
100	SYS_BOOT0 (LCD_D18)	AH26	SYS_BOOT0/ DSS_D18/GPIO_2	I/O	1.8V	Processor SYS_BOOT0. Must be left floating during boot-up, unless the boot order is to be modified. This signal has a 4.7K pull-up on the SOM. See Table 5.1 for more information. This signal is also connected to pin J2.36.

TABLE NOTES:

1. USB voltage levels follow the USB specification and depend on the USB operating speed. Please see the *USB 2.0 Specification* document for more information.

2. This signal is used as card detect on the DM3730 Torpedo Development Kit and is recognized as such by Logic PD software. If using the DM3730/AM3703 Torpedo + Wireless SOM on a custom baseboard that uses an SD card socket without card detect, this signal must be grounded.

3. This signal is on the DM3730/AM3703 processor's VDDS_ CSI2 power rail. On the DM3730/AM3703 Torpedo + Wireless SOM, this rail is powered by the TPS65950's VAUX4 power supply, which is not enabled by default. Therefore, the signal will not function until this power supply is turned on. Also, this signal is only available as an input when configured as a GPIO.

4. These signals are connected to the 5V signals of the standard DM3730/AM3703 Torpedo + Wireless SOM pin-out. Because of this, 0 ohm resistors have been placed on the DM3730/AM3703 Torpedo + Wireless SOM to protect the input signals; these resistors are not populated by default. Custom baseboards must take this into account so as to not provide 5V in on these signals if the 0 ohm resistors are populated on the SOM.

5. This signal is on the DM3730/AM3703 processor's VDDS_ DSI power rail. On the DM3730/AM3703 Torpedo + Wireless SOM, this rail is powered by the TPS65950's VPLL2 power supply, which is not enabled by default. Therefore, the signal will not function until this power supply is turned on.

6. The MIPI DSI pairs must be routed as 100 ohm differential pairs on the baseboard PCB. The length difference between the individual DSI pairs must be matched on the baseboard. Please see Table 4.2 for length matching numbers for the DM3730/AM3703 Torpedo + Wireless SOM.

7. The MIPI CSI2 pairs must be routed as 100 ohm differential pairs on the baseboard PCB. The length difference between the individual CSI2 pairs must be matched on the baseboard. Please see Table 4.3 for length matching numbers for the DM3730/AM3703 Torpedo + Wireless SOM.

7.3 Configurable Pins

Several pins are configurable to allow for maximum customization of the DM3730/AM3703 Torpedo + Wireless SOM feature set. However, tradeoffs must be considered. Table 7.1 gives some examples of features that are gained and lost through customization, although this is not an exhaustive list.

Table 7.1: Feature Gain/Loss through Customization

Resistor Population	Gain	Loss
R92, R94	4 x 4 Keypad	Camera Interface control signals
R91, R93, R95	12-bit Camera Interface	ADC, 4 x 4 Keypad
R86, R138, R140	24-bit LCD	DSI, McSPI1 extra CS
R87, R139, R141	DSI, McSPI1 extra CS	24-bit LCD
R88	McBSP5	McSPI4
R89	McSPI4	McBSP5
R90	ADC	Camera Interface data8-data11
R142, R144, R146, R148	DSI	Parallel LCD
R143, R145, R147, R149	Parallel LCD	DSI

NOTE: Resistor populations other than the default require a custom model number to be created through Logic PD's NPI process. Please contact Logic PD for more information.

Table 7.2 provides a list of all the configurable pins on the J1 and J2 expansion connectors. The information below is the same as what appears in the complete pin description tables in Sections 7.1 and 7.2.

Table 7.2: Configurable J1 and J2 Connector Pins

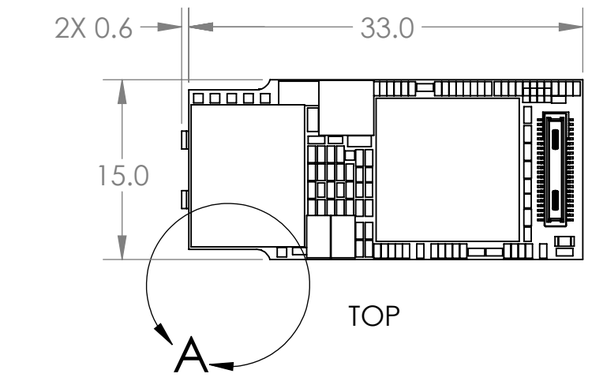
Pin#	Signal Name	BGA Ball#	Processor Signal	I/O	Voltage	Description
J1.76	R90 Populated **(default)**: ADCIN0 (CONFIG11)	H4 (PMIC)	ADCIN0 (PMIC)	I	max 1.5V	Analog to digital converter input. Connected to TPS65950 ADCIN0. Tie to DGND when not used.
	R91 Populated: CSI_D8 (CONFIG11)	K27 (PMIC)	CAM_D8/GPIO_107	I	1.8V	Camera Sensor Interface Data bit 8. This signal may also be used as GPI; output signaling is not supported.
J1.78	R90 Populated **(default)**: ADCIN1 (CONFIG10)	J3 (PMIC)	ADCIN1 (PMIC)	I	max 1.5V	Analog to digital converter input. Connected to TPS65950 ADCIN1. Tie to DGND when not used.
	R91 Populated: CSI_D9 (CONFIG10)	L27	CAM_D9/GPIO_108	I	1.8V	Camera Sensor Interface Data bit 9. This signal may also be used as GPI; output signaling is not supported.
J1.80	R90 Populated **(default)**: ADCIN2 (CONFIG9)	G3 (PMIC)	ADCIN2 (PMIC)	I	max 2.5V	Analog to digital converter input. Connected to TPS65950 ADCIN2. Tie to DGND when not used.
	R91 Populated: CSI_D10 (CONFIG9)	B25	CAM_D10/SSI2_WAKE/ GPIO_109	I	1.8V	Camera Sensor Interface Data bit 10.
J1.82	R90 Populated **(default)**: ADCIN3 (CONFIG8)	P11 (PMIC)	ADCIN3 (PMIC)	I	max 2.5V	Analog to digital converter input. Connected to TPS65950 ADCIN3. Tie to DGND when not used.
	R91 Populated: CSI_D11 (CONFIG8)	C26	CAM_D11/GPIO_110	I	1.8V	Camera Sensor Interface Data bit 11.
J1.86	R86 Populated **(default)**: LCD_D17 (CONFIG1)	H27	DSS_D17/GPIO_87	O	1.8V	LCD data bit when operating in 24 bpp color mode. Please see the *AM/DM37x TRM* for LCD bus mapping.
	R87 Populated: MCSPI1_CS2 (CONFIG1)	AB1	McSPI1_CS2/ MMC3_CLK/ GPIO_176	O	1.8V	McSPI1 interface chip select 2 output.
J1.88	R86 Populated **(default)**: MCSPI3_CLK (CONFIG3)	AE13	ETK_D3/McSPI3_CLK/ MMC3_DAT3/ HSUSB1_DATA7/ HSUSB1_TLL_DATA7/ GPIO_17	O	1.8V	McSPI3 serial clock signal.
	R87 Populated: MCSPI1_CS3 (CONFIG3)	AB2	McSPI1_CS3/ HSUSB2_TLL_DATA2/ MM2_TXDAT/GPIO_177	O	1.8V	McSPI1 interface chip select 3 output.
J2.55	R92 Populated: KEY_ROW3 (CONFIG15)	K7 (PMIC)	KPD.R3 (PMIC)	I	1.8V	Keypad Row 3 signal.

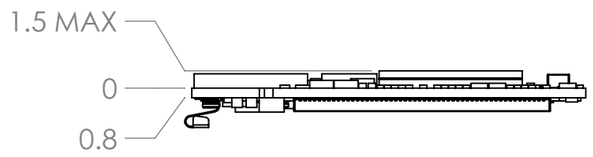
Pin#	Signal Name	BGA Ball#	Processor Signal	I/O	Voltage	Description
	R93 Populated **(default)**: CSI_D7 (CONFIG15)	L28	CAM_D7/GPIO_106	I	1.8V	Camera Sensor Interface Data bit 7. This signal may also be used as GPI; output signaling is not supported.
J2.57	R92 Populated: KEY_ROW2 (CONFIG14)	L8 (PMIC)	KPD.R2 (PMIC)	I	1.8V	Keypad Row 2 signal.
	R93 Populated **(default)**: CSI_D6 (CONFIG14)	K28	CAM_D6/GPIO_105	I	1.8V	Camera Sensor Interface Data bit 6. This signal may also be used as GPI; output signaling is not supported.
J2.61	R92 Populated: KEY_ROW1 (CONFIG13)	K8 (PMIC)	KPD.R1 (PMIC)	I	1.8V	Keypad Row 1 signal.
	R93 Populated **(default)**: CAM_WEN (CONFIG13)	B23	CAM_WEN/ CAM_SHUTTER/ GPIO_167	I	1.8V	Camera Sensor Write Enable.
J2.63	R92 Populated: KEY_ROW0 (CONFIG12)	K9 (PMIC)	KPD.R0 (PMIC)	I	1.8V	Keypad Row 0 signal.
	R93 Populated **(default)**: CSI_HSYNC (CONFIG12)	A24	CAM_HS/ SSI2_DAT_TX/ GPIO_94	I/O	1.8V	Camera Sensor Interface Horizontal Sync signal.
J2.65	R94 populated: KEY_COL3 (CONFIG19)	F7 (PMIC)	KPD.C3 (PMIC)	O	1.8V	Keypad Column 3 signal.
	R95 Populated **(default)**: CSI_VSYNC (CONFIG19)	A23	CAM_VS/ SSI2_FLAG_TX/ GPIO_95	I/O	1.8V	Camera Sensor Interface Vertical Sync signal.
J2.67	R94 Populated: KEY_COL2 (CONFIG18)	G6 (PMIC)	KPD.C2 (PMIC)	O	1.8V	Keypad Column 2 signal.
	R95 Populated **(default)**: CSI_PCLK (CONFIG18)	C27	CAM_PCLK_GPIO_97	I	1.8V	Camera Sensor Interface Pixel Clock signal.
J2.69	R94 Populated: KEY_COL1 (CONFIG17)	H7 (PMIC)	KPD.C1 (PMIC)	O	1.8V	Keypad Column 1 signal.
	R95 Populated **(default)**: CSI_XCLKB (CONFIG17)	B26	CAM_XCLKB/ GPIO_111	O	1.8V	Camera Sensor Clock Output b.
J2.71	R94 Populated: KEY_COL0 (CONFIG16)	G8 (PMIC)	KPD.C0 (PMIC)	O	1.8V	Keypad Column 0 signal.
	R95 Populated **(default)**: CSI_XCLKA (CONFIG16)	C25	CAM_XCLKA/GPIO_96	O	1.8V	Camera Sensor Clock Output a.

Pin#	Signal Name	BGA Ball#	Processor Signal	I/O	Voltage	Description
J2.73	R88 Populated: MCBSP5_DX (CONFIG7)	AF13	ETK_D6/McBSP5_DX/ MMC3_DAT2/ HSUSB1_DATA6/ HSUSB1_TLL_DATA6/ GPIO_20	O	1.8V	McBSP5 interface transmit output.
	R89 Populated **(default)**: MCSPI4_SOMI (CONFIG7)	U21	McBSP1_DR/ McSPI4_SOMI/ McBSP3_DR/ GPIO_159	I	1.8V	McSPI4 interface receive input.
J2.75	R88 Populated: MCBSP5_FSX (CONFIG6)	AH9	ETK_D5/McBSP5_FSX/ MMC3_DAT1/ HSUSB1_DATA5/ HSUSB1_TLL_DATA5/ GPIO_19	I/O	1.8V	McBSP5 transmit frame synchronization.
	R89 Populated **(default)**: MCSPI4_SIMO (CONFIG6)	V21	McBSP1_DX/ McSPI4_SIMO/ McBSP3_DX/ GPIO_158	O	1.8V	McSPI4 interface transmit output.
J2.77	R88 Populated: MCBSP5_DR (CONFIG5)	AE11	ETK_D4/McBSP5_DR/ MMC3_DAT0/ HSUSB1_DATA4/ HSUSB1_TLL_DATA4/ GPIO_18	I	1.8V	McBSP5 interface receive input.
	R89 Populated **(default)**: MCSPI4_CLK (CONFIG5)	Y21	McBSP1_CLKR/ McSPI4_CLK/ SIM_CD/GPIO_156	O	1.8V	McSPI4 serial clock signal.
J2.79	R143 Populated **(default)**: LCD_D2 (B3)(CONFIG20)	E28	DSS_D20/SDI_DEN/ McSPI3_SOMI/ DSS_D2/GPIO_90	O	1.8V	LCD B3 data bit when operating in 16 bpp 5:6:5 color mode. Please see the *AM/DM37x TRM* for 24-bit LCD bus mapping.
	R142 Populated: DSI_DX0 (CONFIG20)	AG22	DSS_D0/UART1_CTS/ DX0/GPIO_70	O	1.8V (VPLL2) (see note 5)	MIPI DSI DX0 output. Route as differential pair with DSI_DY0. Route pair with 100 ohms differential impedance. (See note 6)
J2.81	R145 Populated **(default)**: LCD_D3 (B4)(CONFIG21)	J26	DSS_D21/SDI_STP/ McSPI3_CS0/ DSS_D3/GPIO_91	O	1.8V	LCD B4 data bit when operating in 16 bpp 5:6:5 color mode. Please see the *AM/DM37x TRM* for 24-bit LCD bus mapping.
	R144 Populated: DSI_DY0 (CONFIG21)	AH22	DSS_D1/UART1_RTS/ DY0/GPIO_71	O	1.8V (VPLL2) (see note 5)	MIPI DSI DY0 output. Route as differential pair with DSI_DX0. Route pair with 100 ohms differential impedance. (See note 6)
J2.82	R138 Populated **(default)**: LCD_D10 (G5)(CONFIG24)	AD28	DSS_D10/SDI_DAT1N/ GPIO_80	O	1.8V	LCD G5 data bit when operating in 16 bpp 5:6:5 color mode. Please see the *AM/DM37x TRM* for 24-bit LCD bus mapping.
	R139 Populated: DSI_DX2 (CONFIG24)	AG24	DSS_D4/UART3_RX_IRRX/DX2/GPIO_74	O	1.8V (VPLL2) (see note 5)	MIPI DSI DX2 output. Route as differential pair with DSI_DY2. Route pair with 100 ohms differential impedance. (See note 6)

Pin#	Signal Name	BGA Ball#	Processor Signal	I/O	Voltage	Description
J2.84	R140 Populated **(default)**: LCD_D11 (R1)(CONFIG25)	AD27	DSS_D11/ SDI_DAT1P/GPIO_81	O	1.8V	LCD R1 data bit when operating in 16 bpp 5:6:5 color mode. Please see the *AM/DM37x TRM* for 24-bit LCD bus mapping.
	R141 Populated: DSI_DY2 (CONFIG25)	AH24	DSS_D5/UART3_TX_IR TX/DY2/GPIO_75	O	1.8V (VPLL2) (see note 5)	MIPI DSI DY2 output. Route as differential pair with DSI_DX2. Route pair with 100 ohms differential impedance. (See note 6)
J2.94	R146 Populated: DSI_DX1 (CONFIG22)	AG23	DSS_D2/DX1/GPIO_72	O	1.8V (VPLL2) (see note 5)	MIPI DSI DX1 output. Route as differential pair with DSI_DY1. Route pair with 100 ohms differential impedance. (See note 6)
	R147 Populated **(Default)**: LCD_D4 (B5) (CONFIG22)	AC27	DSS_D22/SDI_CLKP/ McSPI3_CS1/DSS_D4/ GPIO_92	O	1.8V	LCD B5 data bit when operating in 16 bpp 5:6:5 color mode. Please see the *AM/DM37x TRM* for 24-bit LCD bus mapping.
J2.96	R148 Populated: DSI_DY1 (CONFIG23)	AH23	DSS_D3/DY1/GPIO_73	O	1.8V (VPLL2) (see note 5)	MIPI DSI DY1 output. Route as differential pair with DSI_DX1. Route pair with 100 ohms differential impedance. (See note 6)
	R149 Populated **(Default)**: LCD_D5 (G0) (CONFIG23)	AC28	DSS_D23/SDI_CLKN/ DSS_D5/GPIO_93	O	1.8V	LCD G0 data bit when operating in 16 bpp 5:6:5 color mode. Please see the *AM/DM37x TRM* for 24-bit LCD bus mapping.

Appendix A: DM3730/AM3703 Torpedo + Wireless SOM Mechanical Drawing

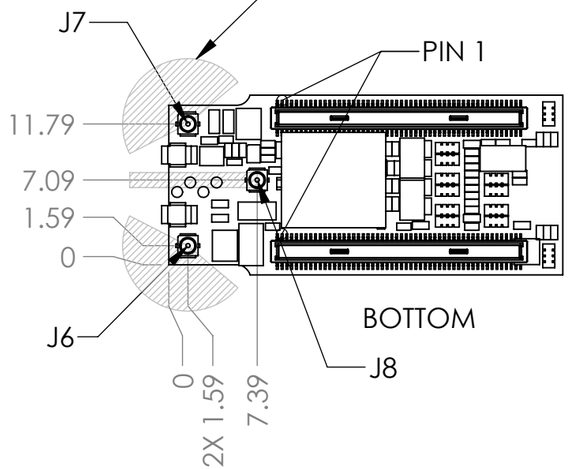


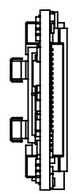


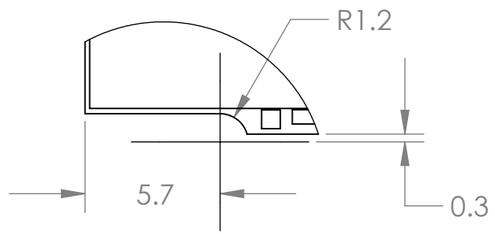
REVISIONS			
REV.	PCB NUMBER	DESCRIPTION	DATE
A	1020005	INITIAL RELEASE	08.16.11
B	1020612	UPDATE TO REFLECT NEW PCB NUMBER	11.10.11
C	1021713	NEW PCB NUMBER, ADD GROUNDING TABS AND COAX AREAS	04.20.12
D	1021713	ADDED HOLD DOWN CLIP KEEPOUT, COAX BASEBOARD KEEPOUT	05.02.12
E	1021713	EDITED ETM BOARD HEIGHT	06.21.12
F	1021713	ADDED GROUNDING CLIP OVERHANG DIMENSION	09.10.12
G	1021713	UPDATED CABLE ROUTING NOTE, ETM BOARD CLEARANCE	04.19.13
H	1021713	UPDATED CONNECTOR ORIGIN TO DENOTE A TOLERANCE OF ±0.1. WAS: 0; IS: 0.00	05.14.13

NOTES:

1. DO NOT SCALE DRAWING
2. DO NOT PLACE ANY COMPONENTS OR EXPOSED VIAS WITHIN LAYOUT AREA OF SOM
3. BASEBOARD CONNECTOR SPECIFICATION (MACHINE PLACEMENT RECOMMENDED): HIROSE DF40C-100DS-0.4V
4. IF USING THE ETM DEBUG BOARD DURING DEVELOPMENT, VERIFY COMPONENT HEIGHT CONSTRAINTS IN SPECIFIED AREA
5. PANEL VESTIGES ON ALL FOUR EDGES - DO NOT PLACE COMPONENTS DIRECTLY ALIGNED WITH EDGE OF SOM







DETAIL A
SCALE 4 : 1

THIS DRAWING PREPARED IN ACCORDANCE WITH ASME Y14.5-2000

ALL DIMENSIONS ARE IN MILLIMETERS UNLESS OTHERWISE SPECIFIED

TOLERANCES UNLESS OTHERWISE SPECIFIED

X	± 0.5
X.X	± 0.2
X.XX	± 0.1
X°	± 1°

THIRD ANGLE PROJECTION

ENG	KAG
DATE	5/2/2012
CHECK	NWR
DATE	5/2/2012
MGR	LLL
DATE	6/3/2013
MANF	
DATE	

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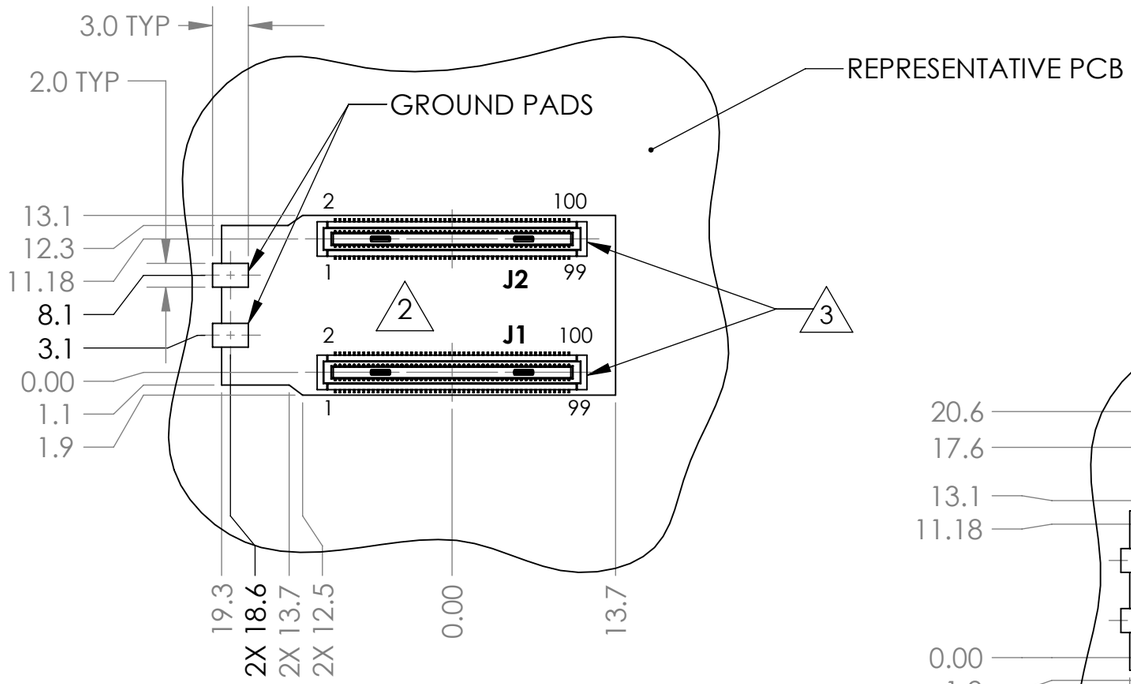
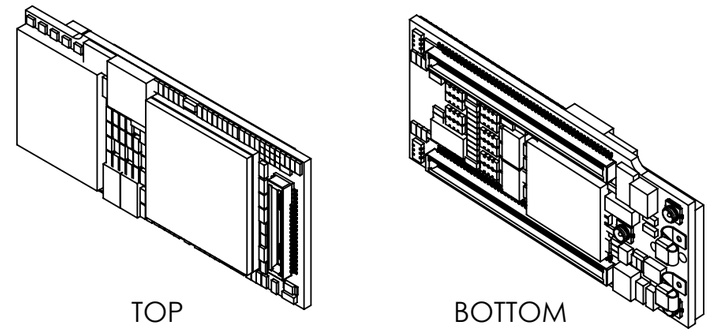
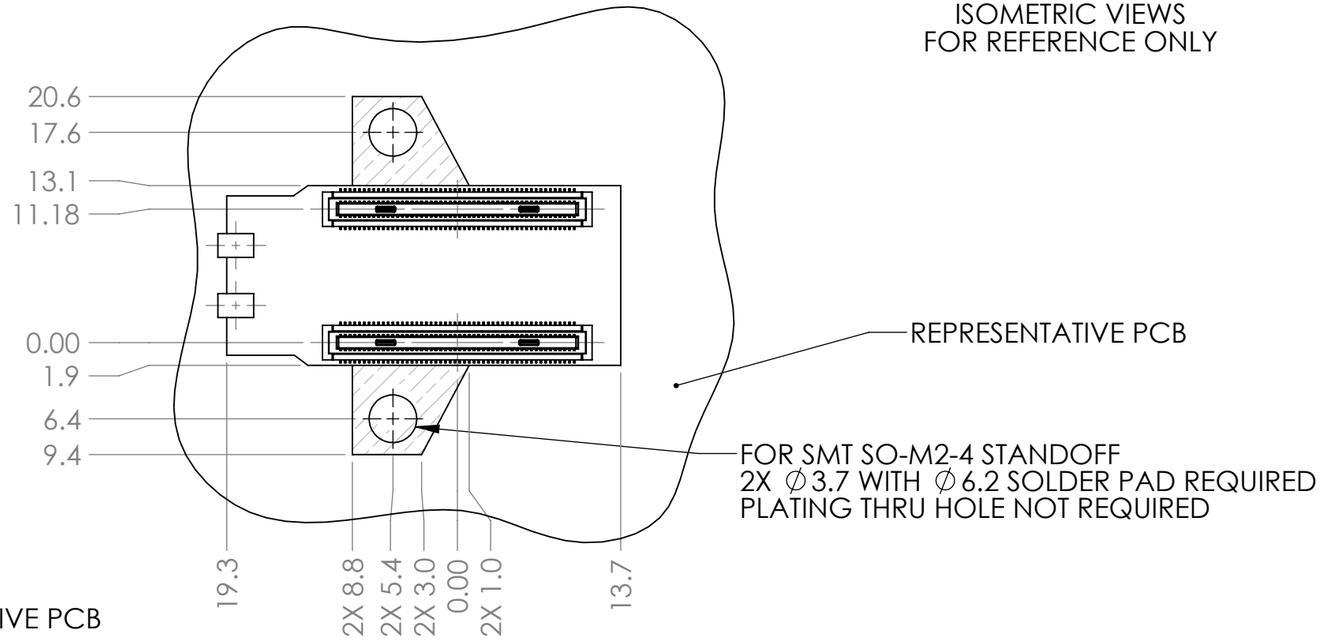
SIZE	TITLE	REV
B	DM3730 & AM3703 TORPEDO + WIRELESS SOM	H
SCALE	DWG NO	SHEET
2:1	1020244	1 OF 3



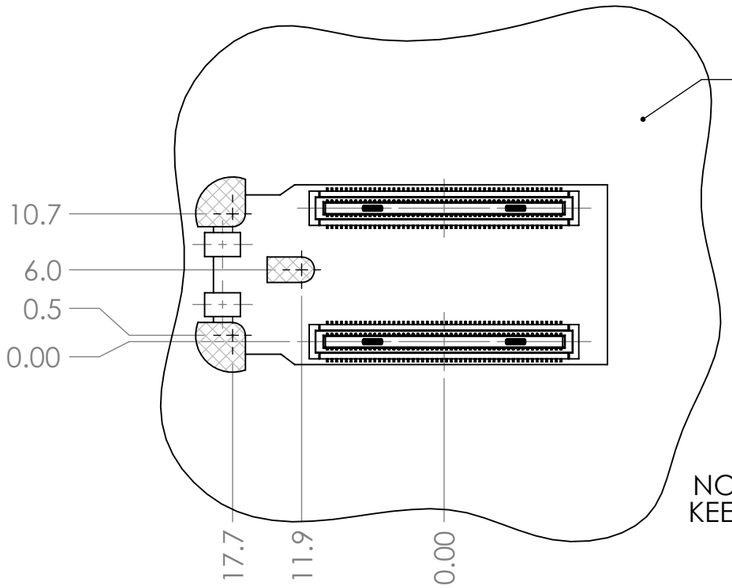
BASIC RECOMMENDED KEEPOUT AREA AND BASEBOARD FOOTPRINT



ISOMETRIC VIEWS
FOR REFERENCE ONLY

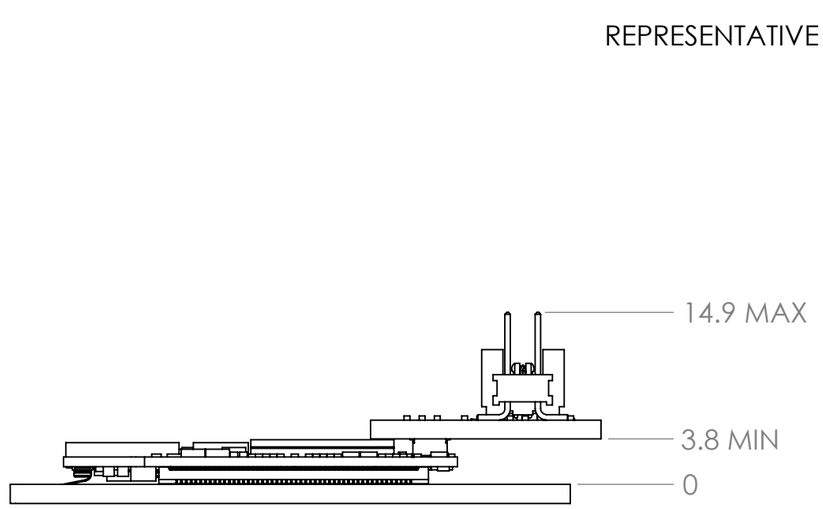


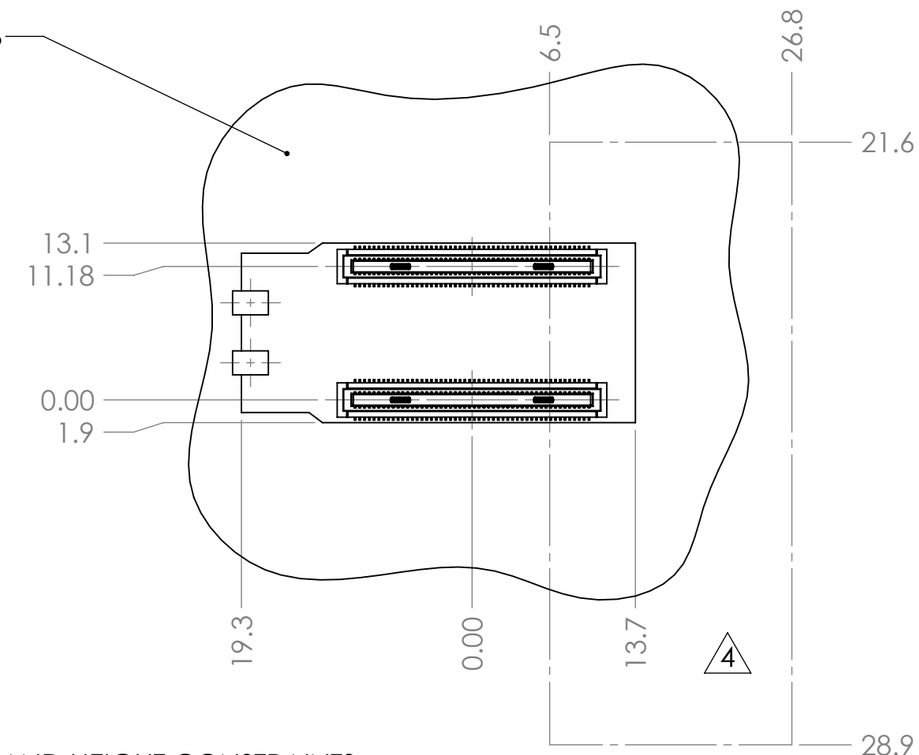
ADDITIONAL KEEPOUT AREA AND BASEBOARD FOOTPRINT FOR HOLD DOWN CLIP



NOMINAL RECOMMENDED VIA AND TRACE KEEPOUT AREA DEPENDING ON CABLE USED AND ROUTING

SIZE	TITLE	REV
B	DM3730 & AM3703 TORPEDO + WIRELESS SOM	H
SCALE	DWG NO	SHEET
2:1	1020244	2 OF 3





ETM DEBUG BOARD OUTLINE AND HEIGHT CONSTRAINTS

SIZE	TITLE	REV
B	DM3730 & AM3703 TORPEDO + WIRELESS SOM	H
SCALE	DWG NO	SHEET
2:1	1020244	3 OF 3